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(12) **United States Design Patent**
Herbst et al.

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(45) **Date of Patent:** **** Aug. 8, 2017**

(54) **MOUNT FOR ELECTRONIC DEVICE**

DESCRIPTION

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(**) Term: **15 Years**

(21) Appl. No.: **29/552,864**

(22) Filed: **Jan. 26, 2016**

(51) **LOC (10) Cl.** **14-03**

(52) **U.S. Cl.**
USPC **D14/217**

(58) **Field of Classification Search**
USPC D14/253, 251, 240, 217, 496, 440, 423,
D14/447, 439, 432; D12/415-426.1
(Continued)

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(Continued)

Primary Examiner — Ian Simmons

Assistant Examiner — Khawaja Anwar

(74) *Attorney, Agent, or Firm* — Patterson + Sheridan,
LLP

(57) **CLAIM**

The ornamental design for a mount for an electronic device,
as shown and described.

FIG. 1 is a top front perspective view of a mount for an electronic device showing our new design according to a first embodiment;
FIG. 2 is a bottom front perspective view thereof;
FIG. 3 a top rear perspective view thereof;
FIG. 4 is a bottom rear perspective view thereof;
FIG. 5 is a front elevational view thereof;
FIG. 6 is a right side elevational view thereof;
FIG. 7 is a rear elevational view thereof;
FIG. 8 is a left side elevational view thereof;
FIG. 9 is a top plan view thereof;
FIG. 10 is a bottom plan view thereof;
FIG. 11 is a top front perspective view of the mount in an open position;
FIG. 12 is a bottom front perspective view thereof;
FIG. 13 a top rear perspective view thereof;
FIG. 14 is a bottom rear perspective view thereof;
FIG. 15 is a right side elevational view thereof;
FIG. 16 is a front elevational view thereof;
FIG. 17 is a rear elevational view thereof;
FIG. 18 is a top plan view thereof; and
FIG. 19 is a top perspective view of a portion of a top surface of the mount;
FIG. 20 is a top front perspective view of a mount for an electronic device showing our new design according to a second embodiment;
FIG. 21 is a bottom front perspective view thereof;
FIG. 22 a top rear perspective view thereof;
FIG. 23 is a bottom rear perspective view thereof;
FIG. 24 is a front elevational view thereof;
FIG. 25 is a right side elevational view thereof;
FIG. 26 is a rear elevational view thereof;
FIG. 27 is a left side elevational view thereof;
FIG. 28 is a top plan view thereof;
FIG. 29 is a bottom plan view thereof;
FIG. 30 is a top front perspective view of the mount in an open position;
FIG. 31 is a bottom front perspective view thereof;
FIG. 32 a top rear perspective view thereof;
FIG. 33 is a bottom rear perspective view thereof;
FIG. 34 is a right side elevational view thereof;
FIG. 35 is a front elevational view thereof;

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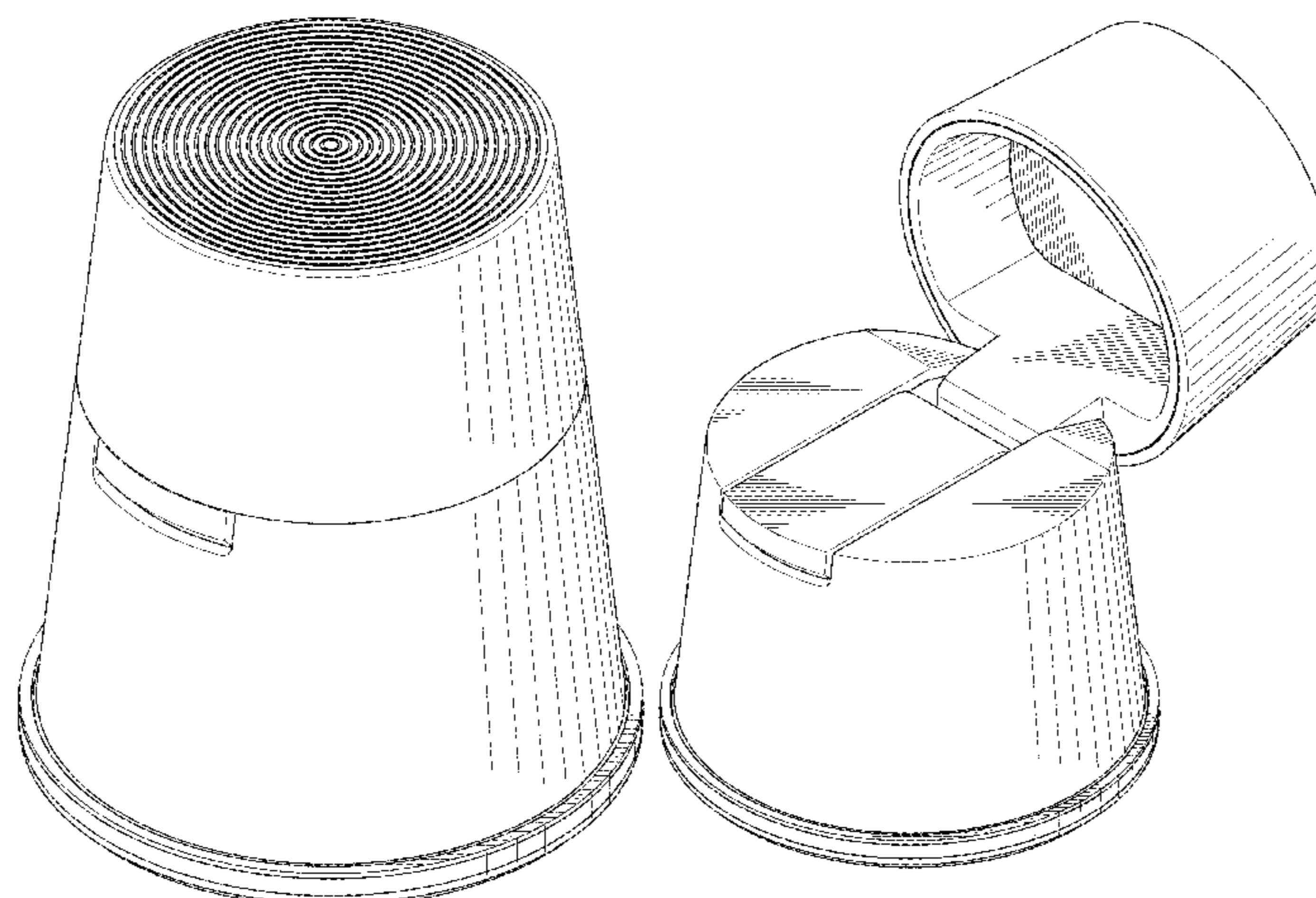


FIG. 36 is a rear elevational view thereof;
FIG. 37 is a top plan view thereof; and,
FIG. 38 is a top perspective view of a portion of a top surface
of the mount.
The portions illustrated in broken lines form no part of the
claimed design.

1 Claim, 38 Drawing Sheets

(58) **Field of Classification Search**

CPC .. H04M 1/04; H04M 1/6075; H04M 1/72569;
H04M 1/72577; H04M 17/026; H04M
1/006; H04M 1/0214; H04M 1/0233;
H04M 1/0254; H04M 1/0264; H04M
1/0279; H04M 1/18; H04M 1/6091;
H04M 1/723; H04M 1/725; H04M

2207/206; H04M 2250/16; H04W 4/046;
H04W 4/22; H04W 76/007; H04W
76/028

See application file for complete search history.

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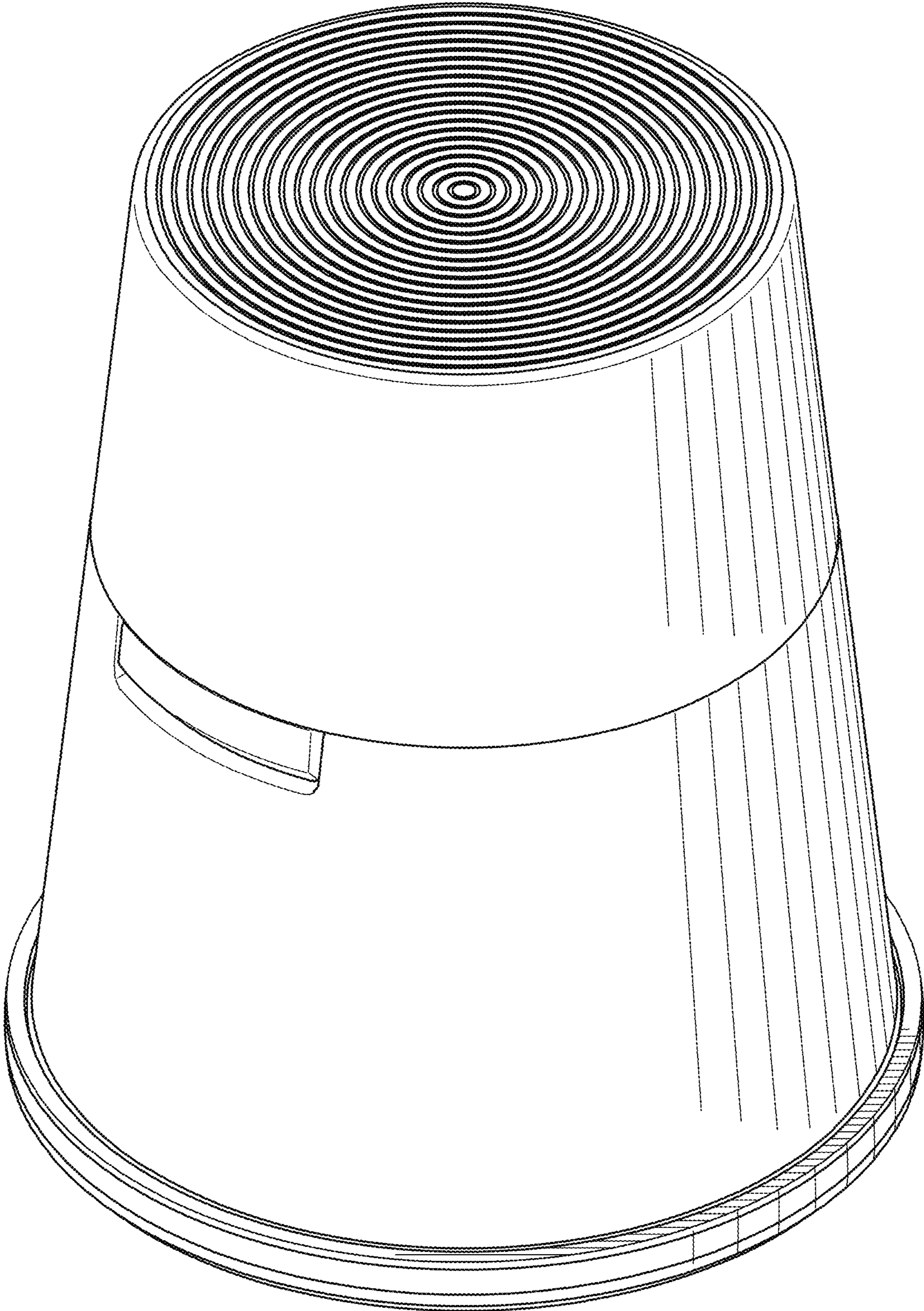


Fig. 1

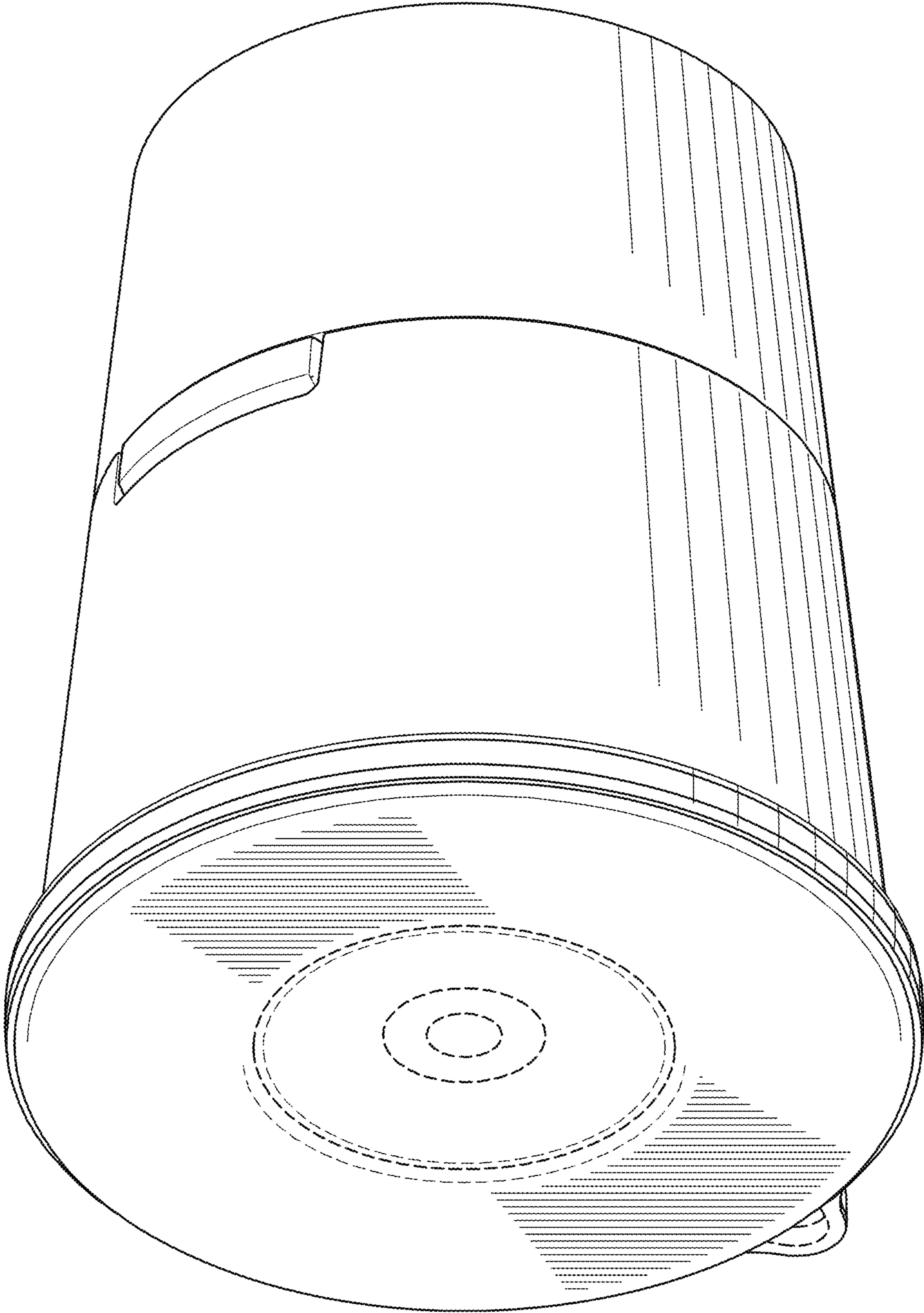


Fig. 2

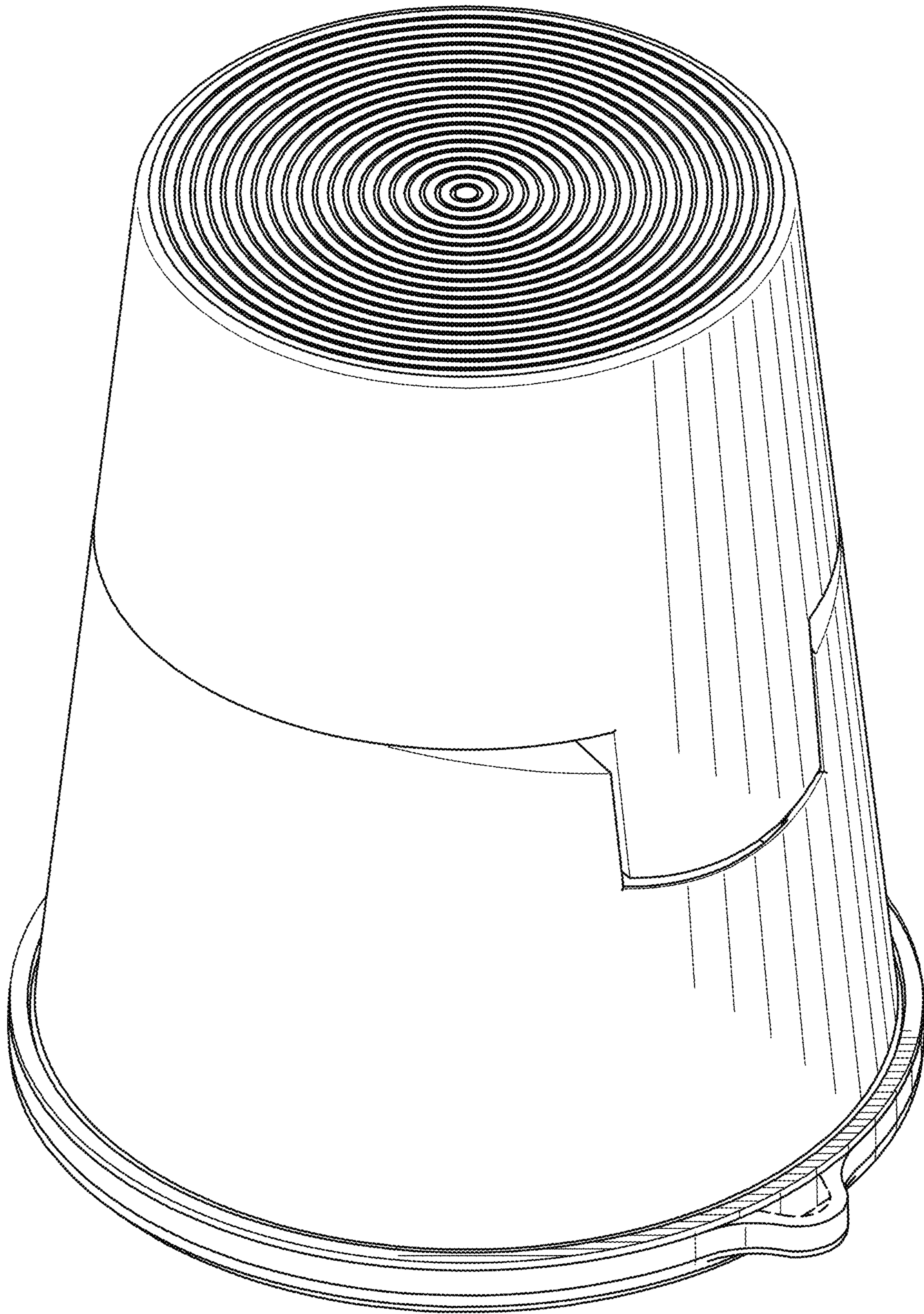


Fig. 3

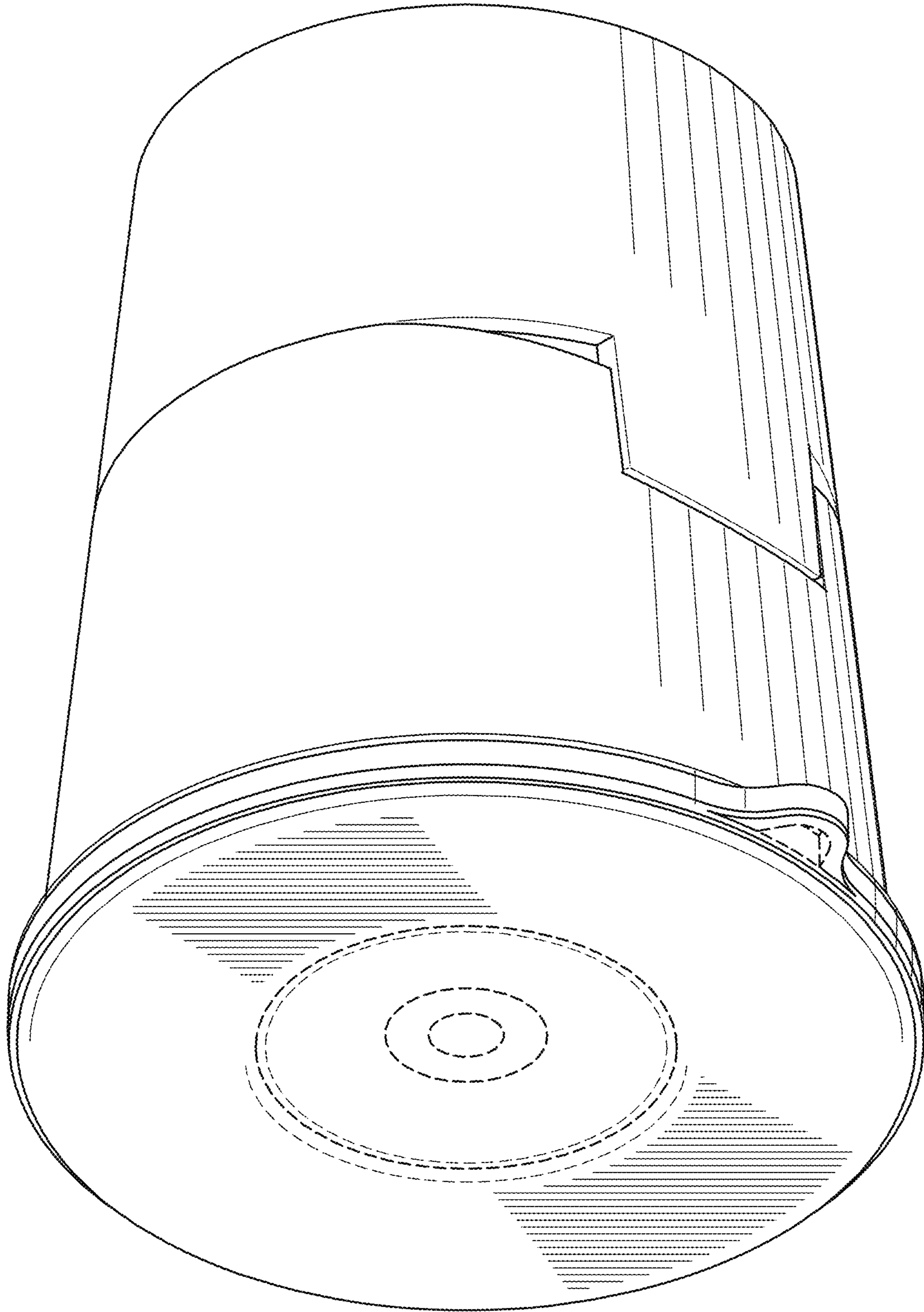


Fig. 4

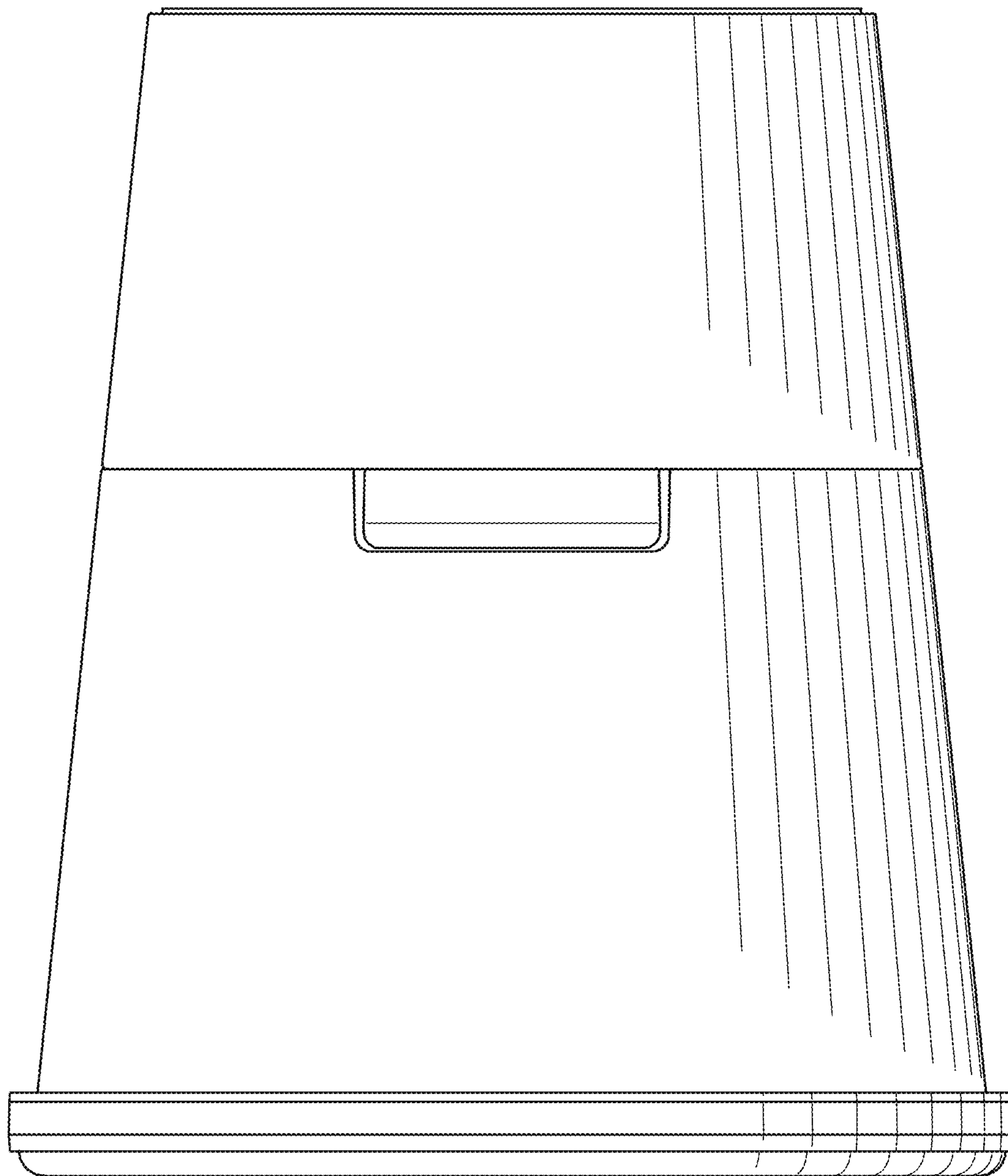


Fig. 5

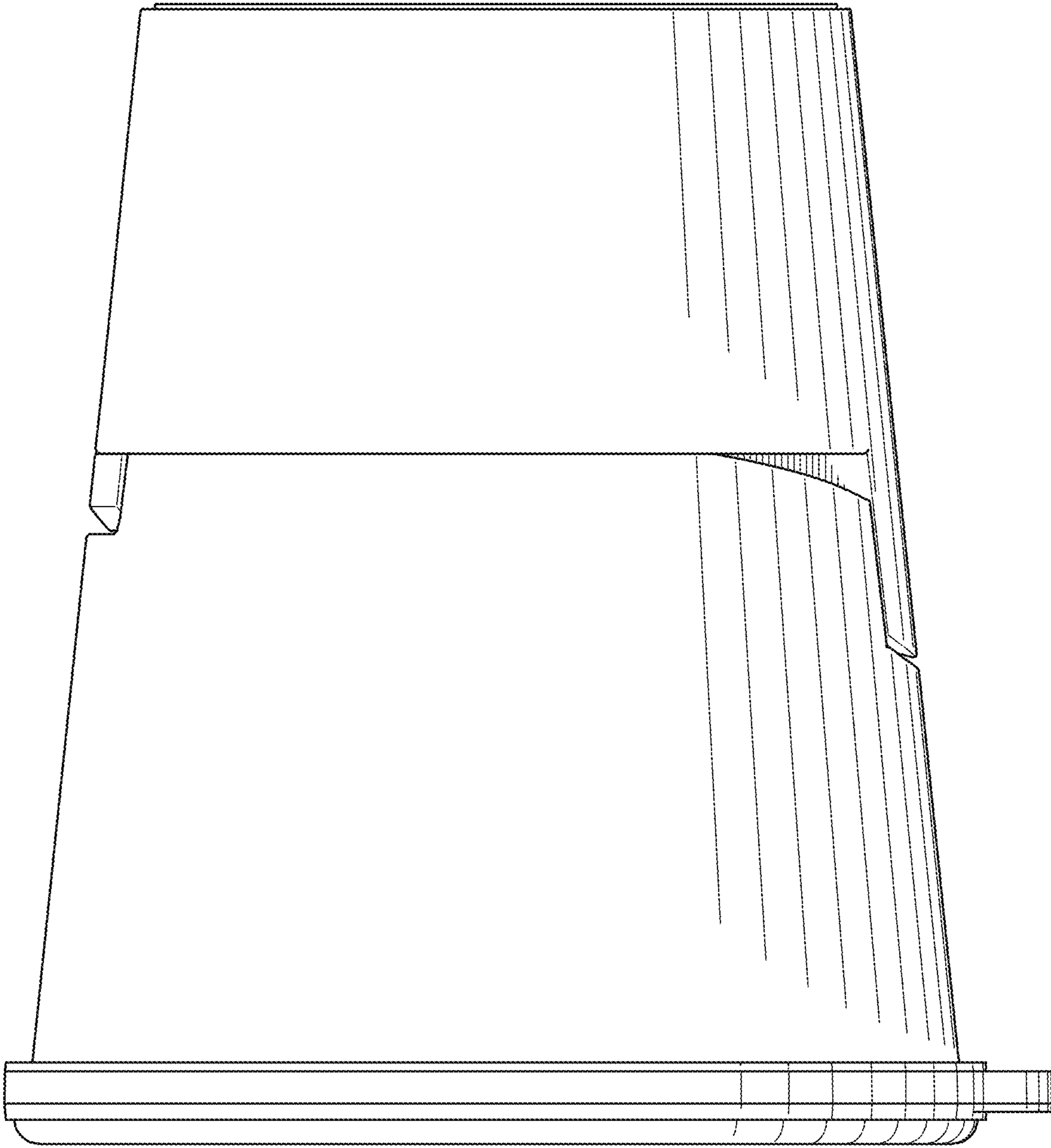


Fig. 6

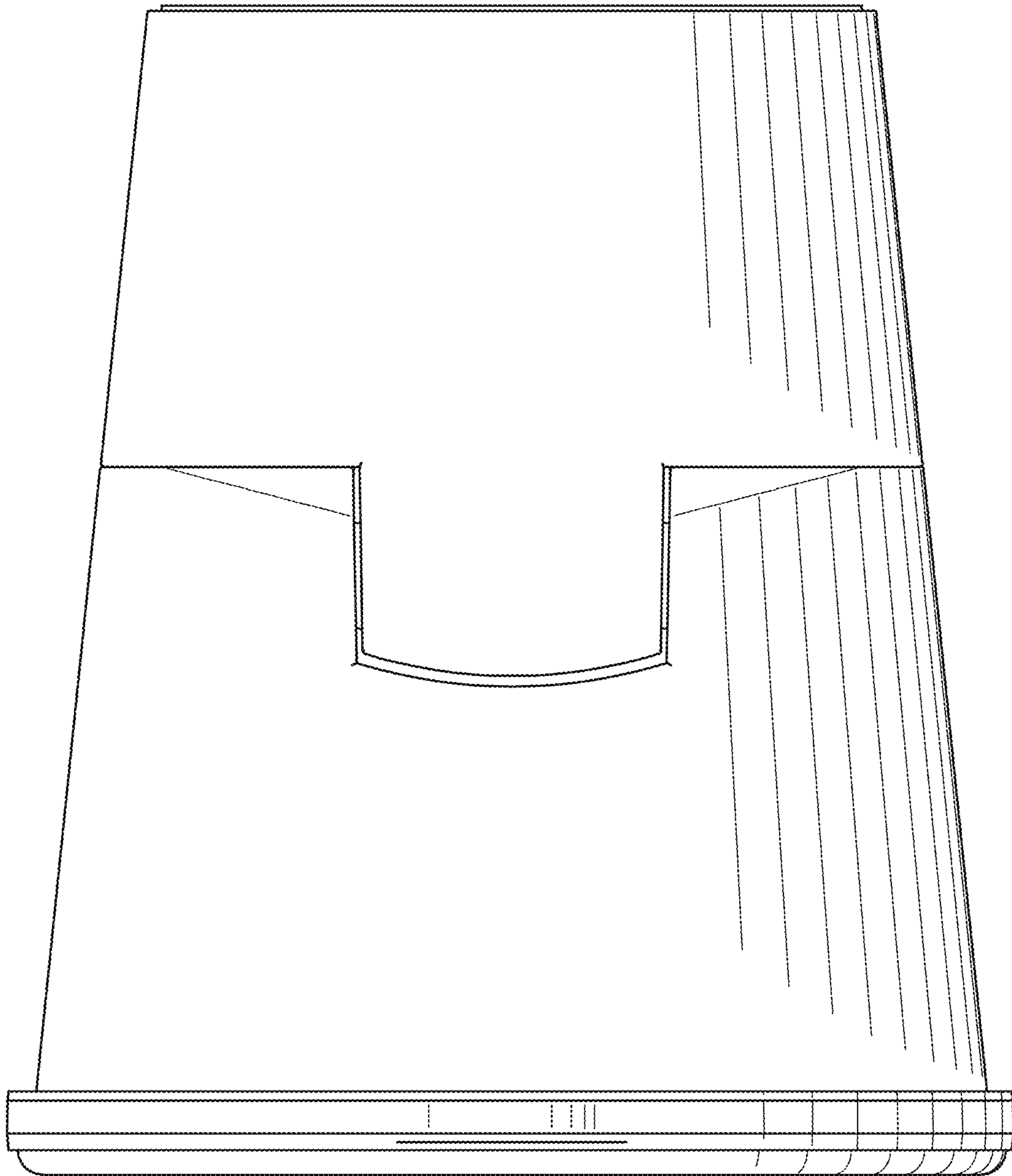


Fig. 7

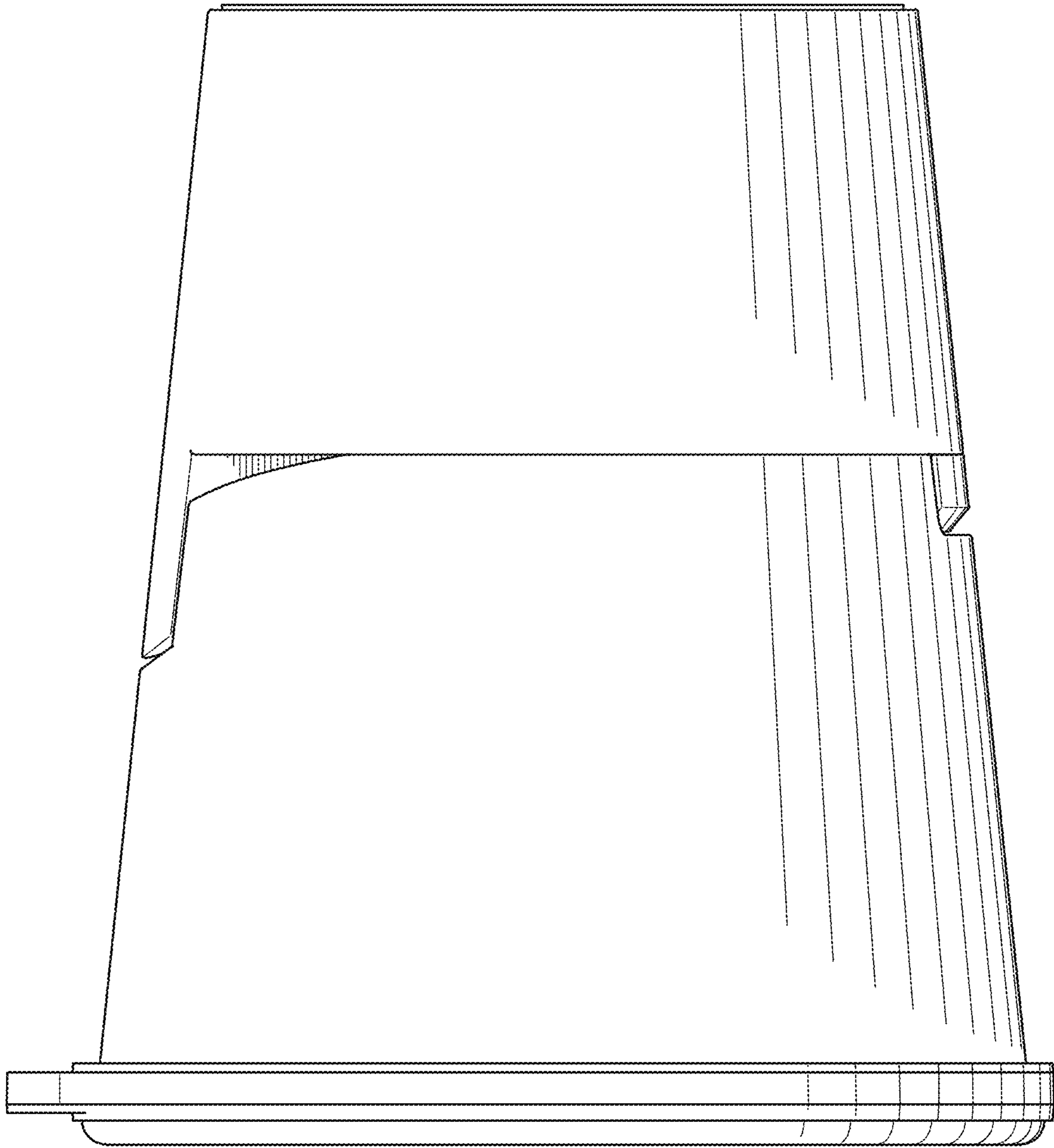


Fig. 8

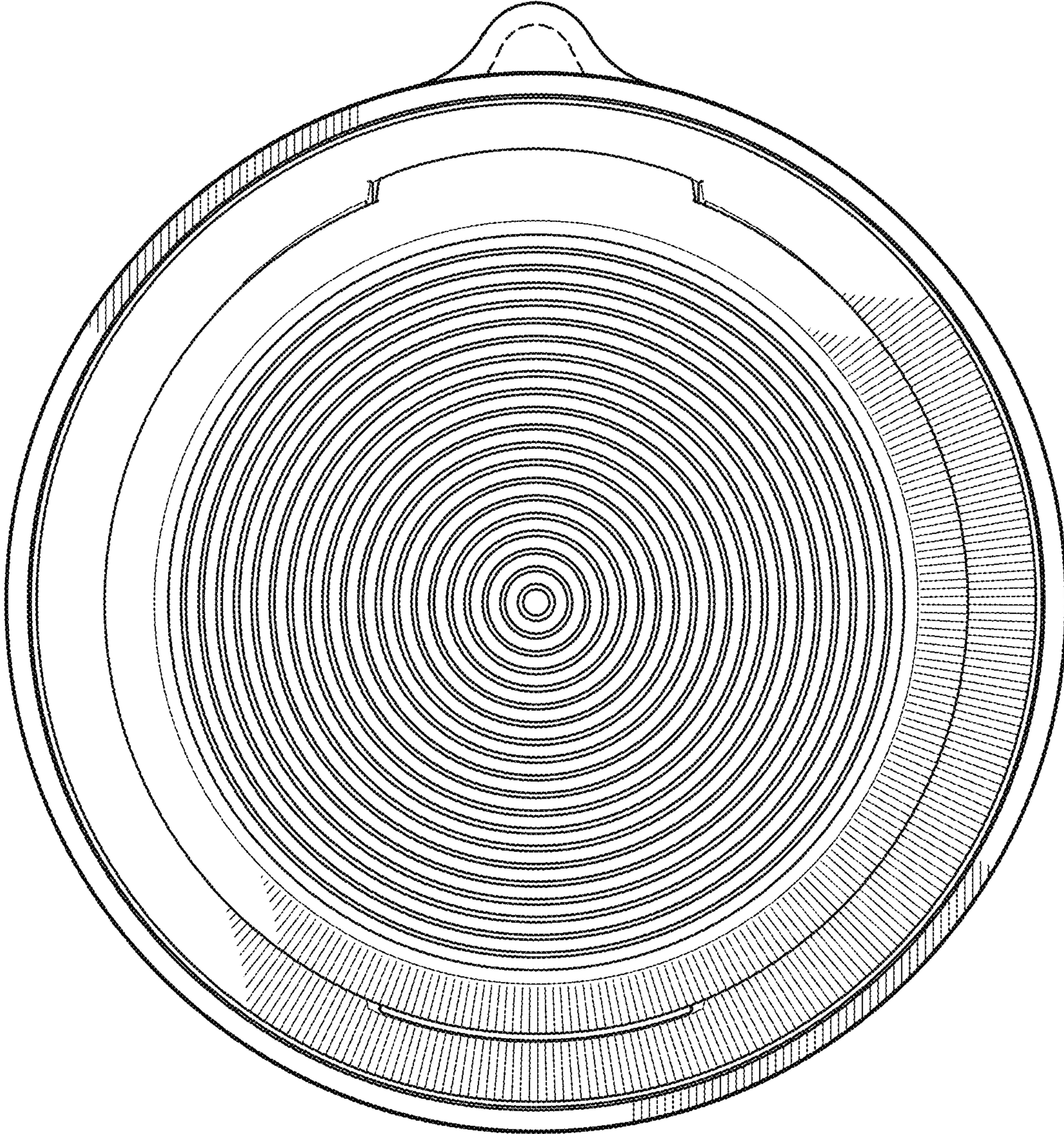


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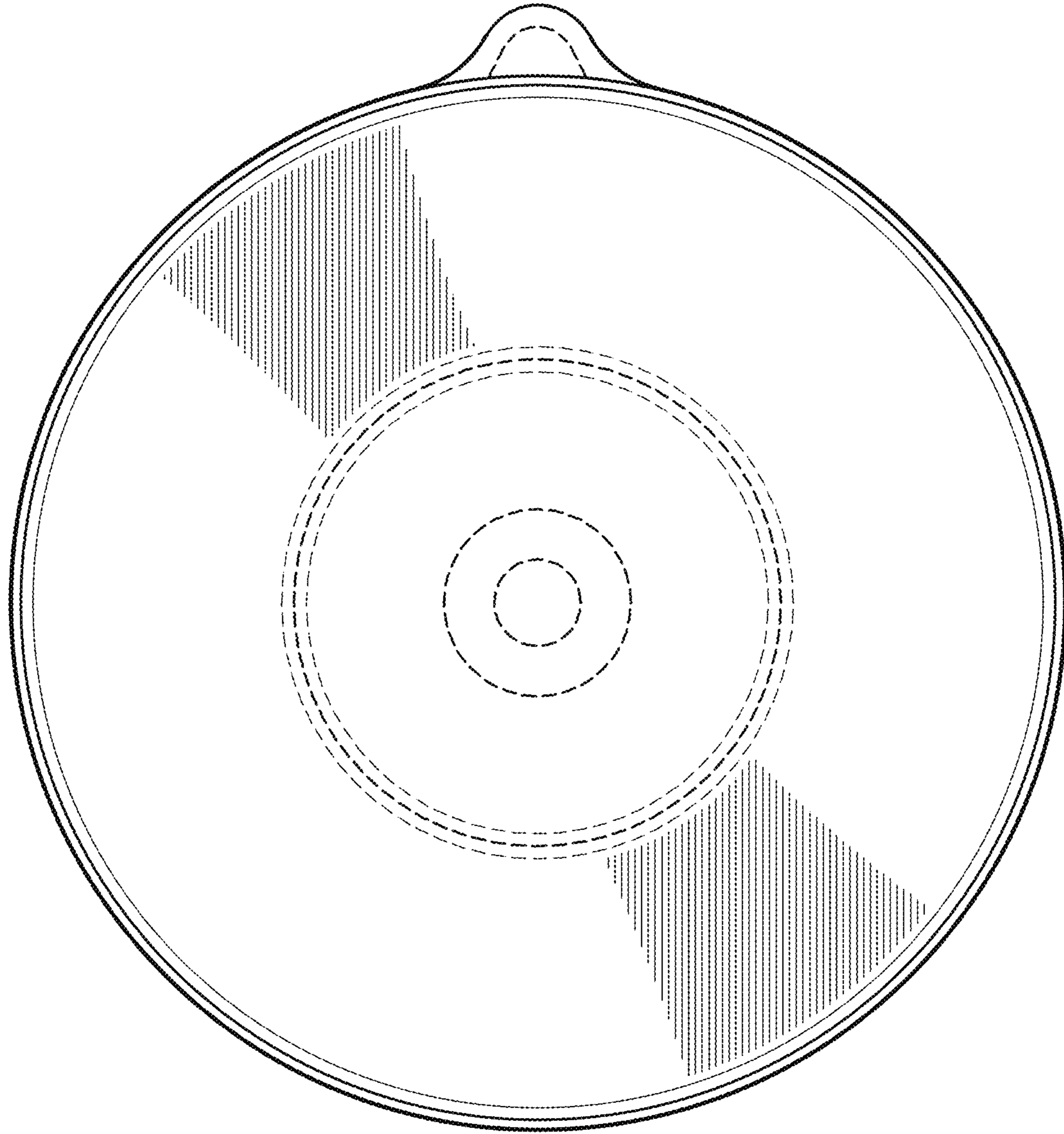


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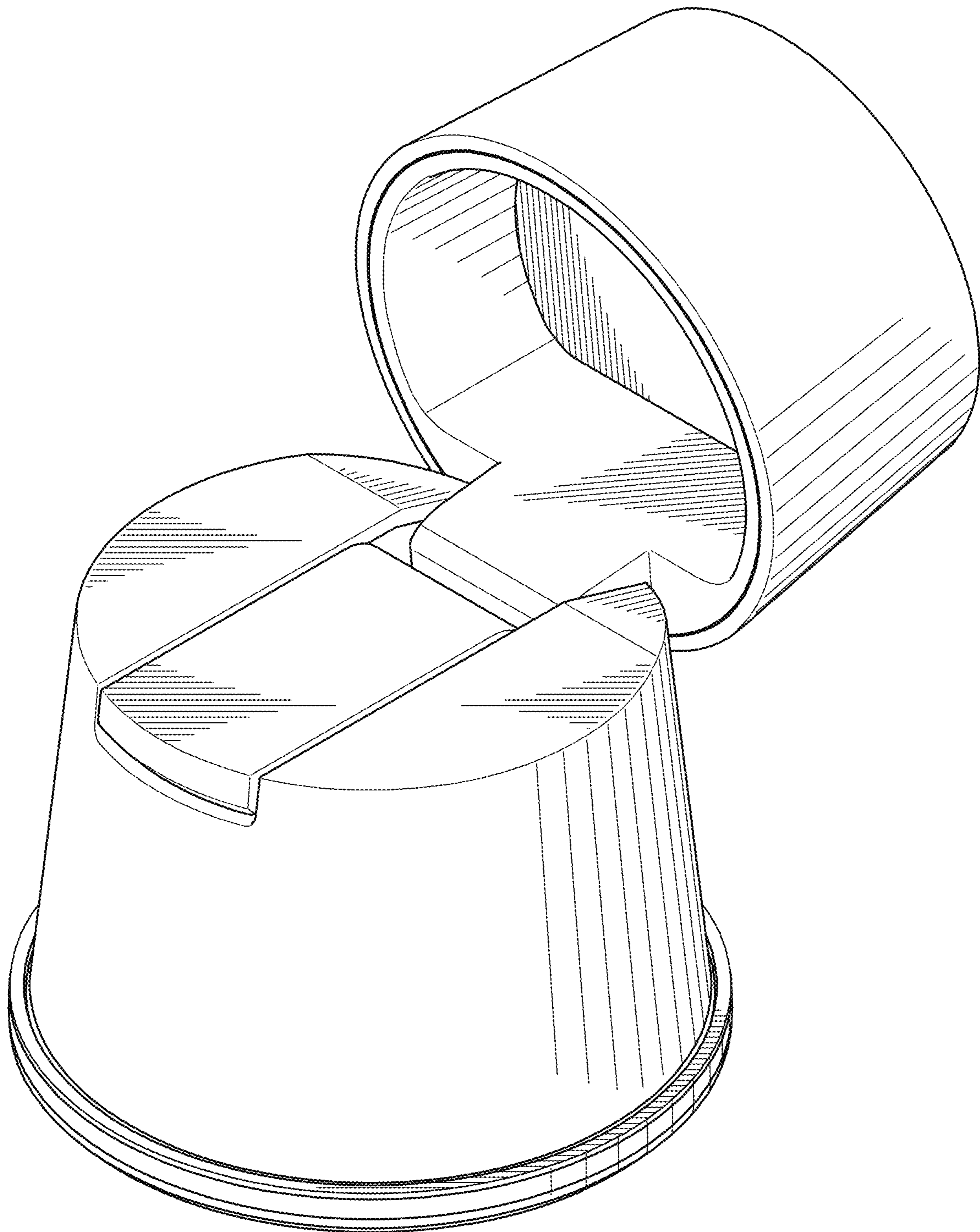


Fig. 11

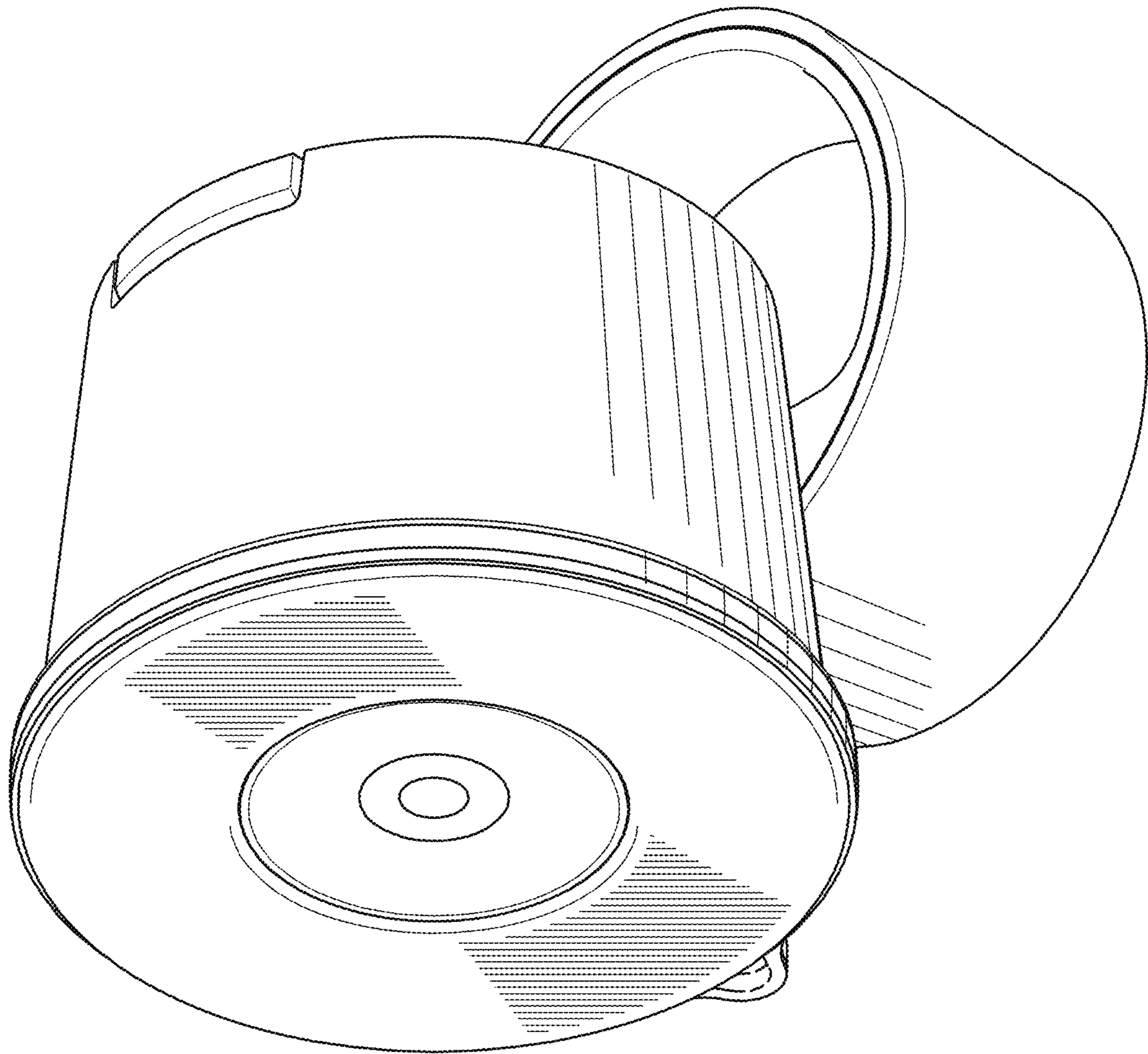


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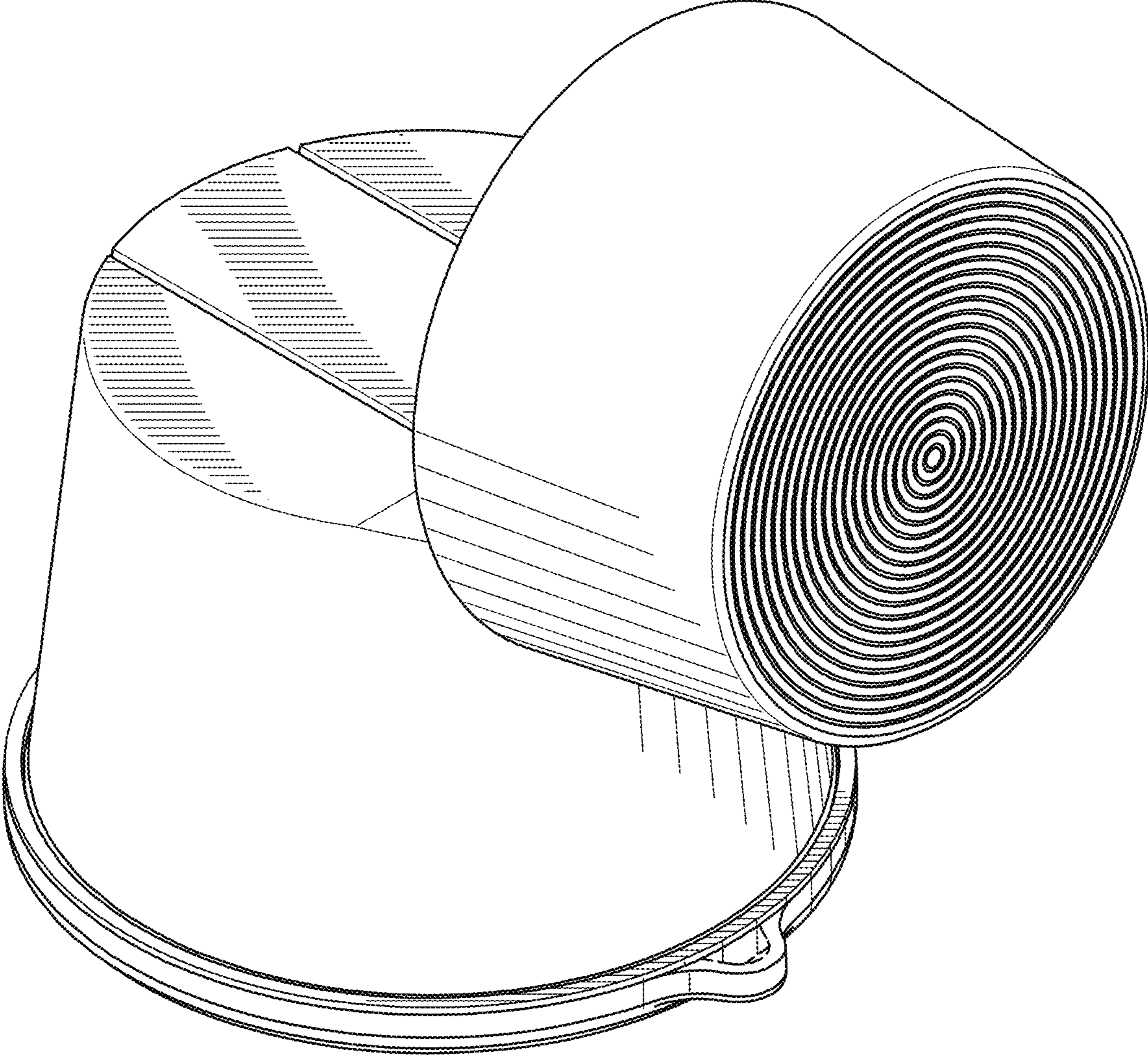


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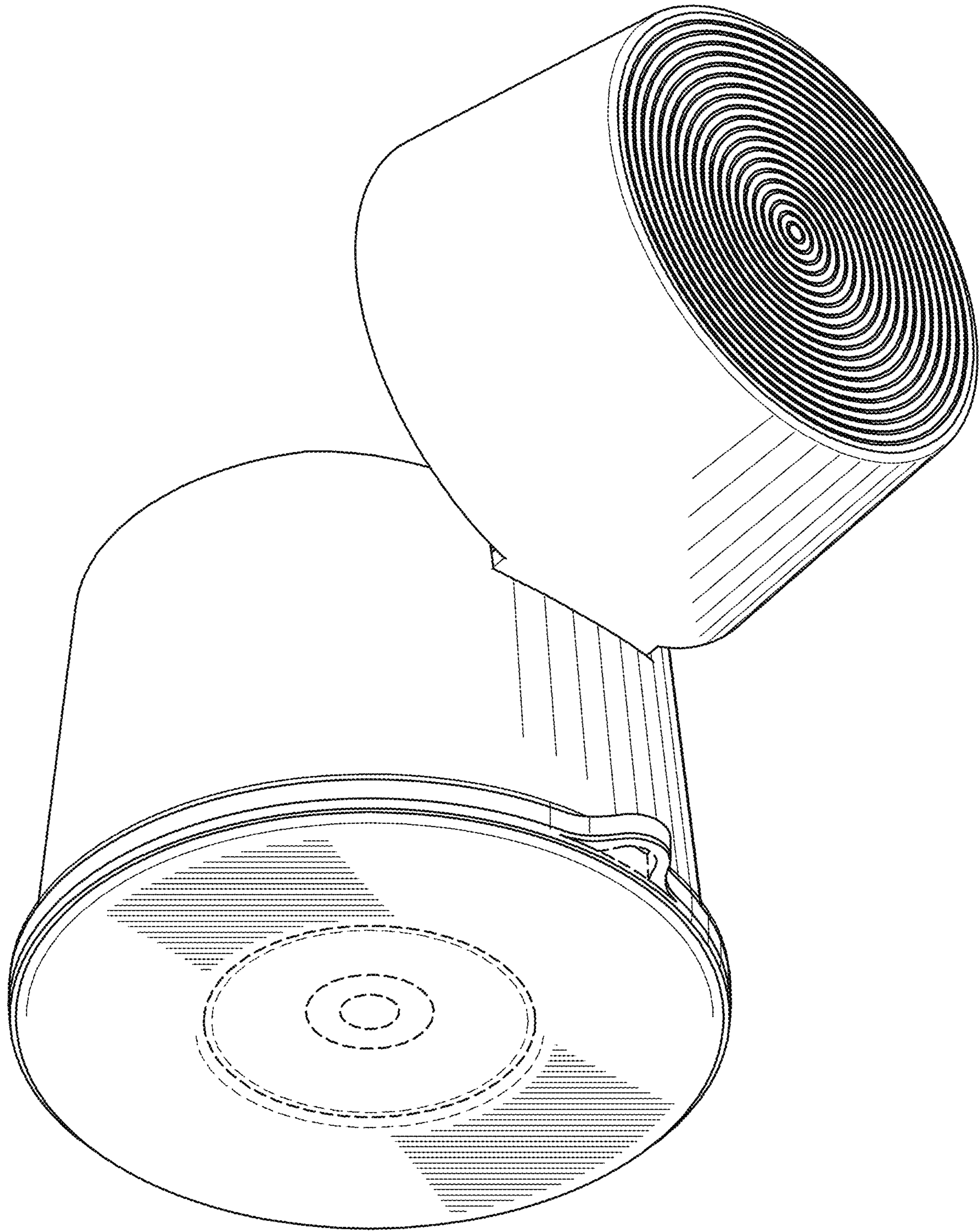


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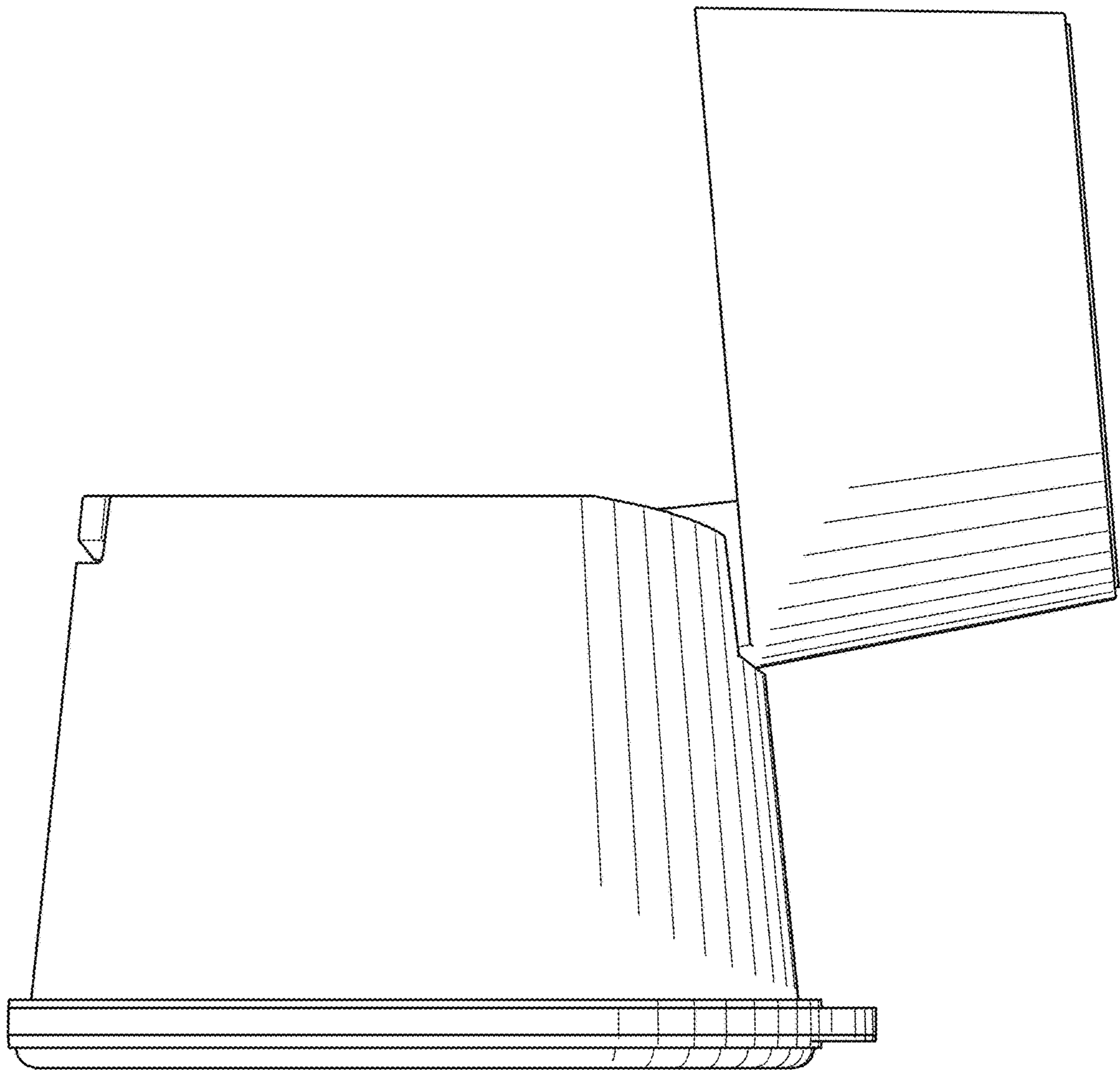


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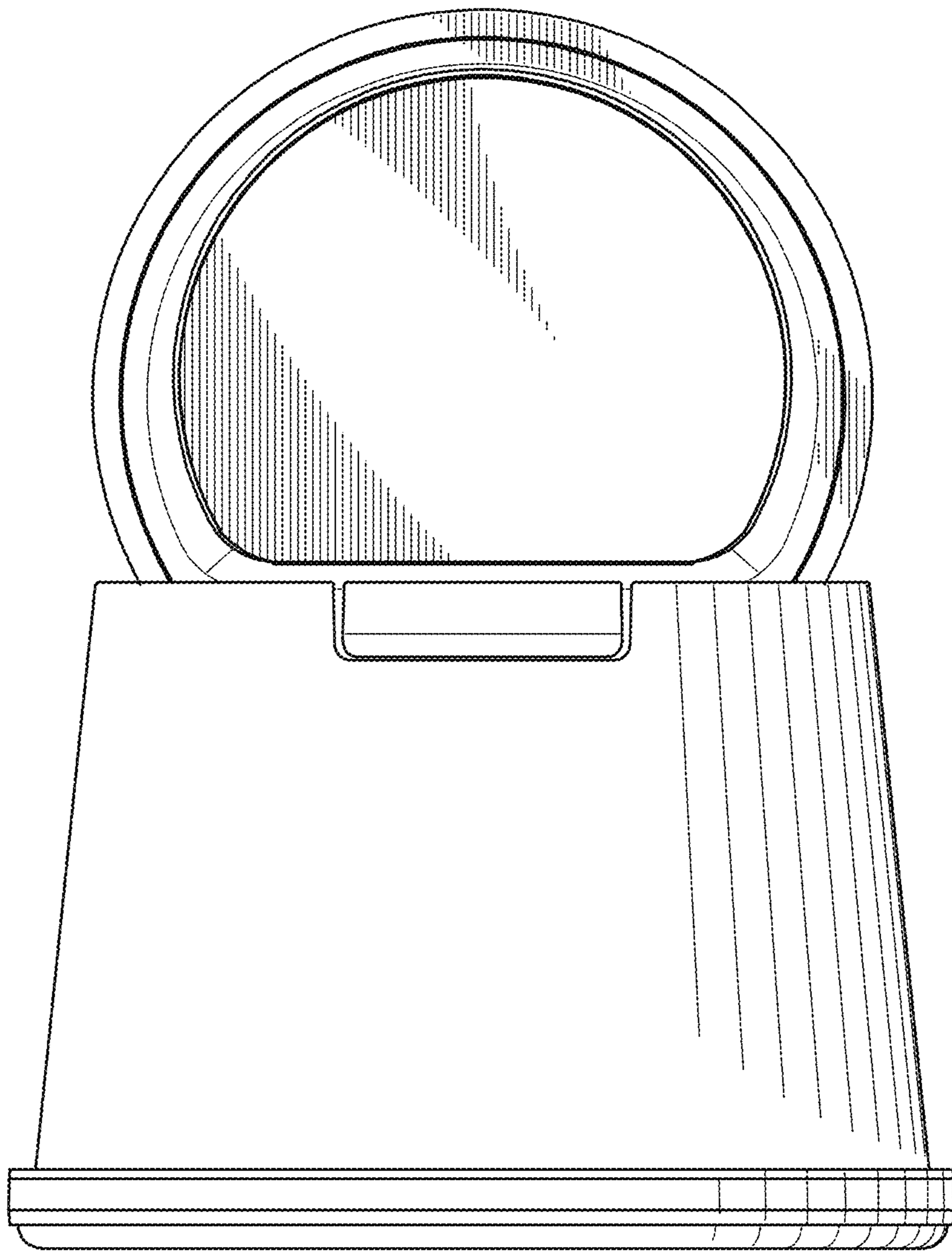


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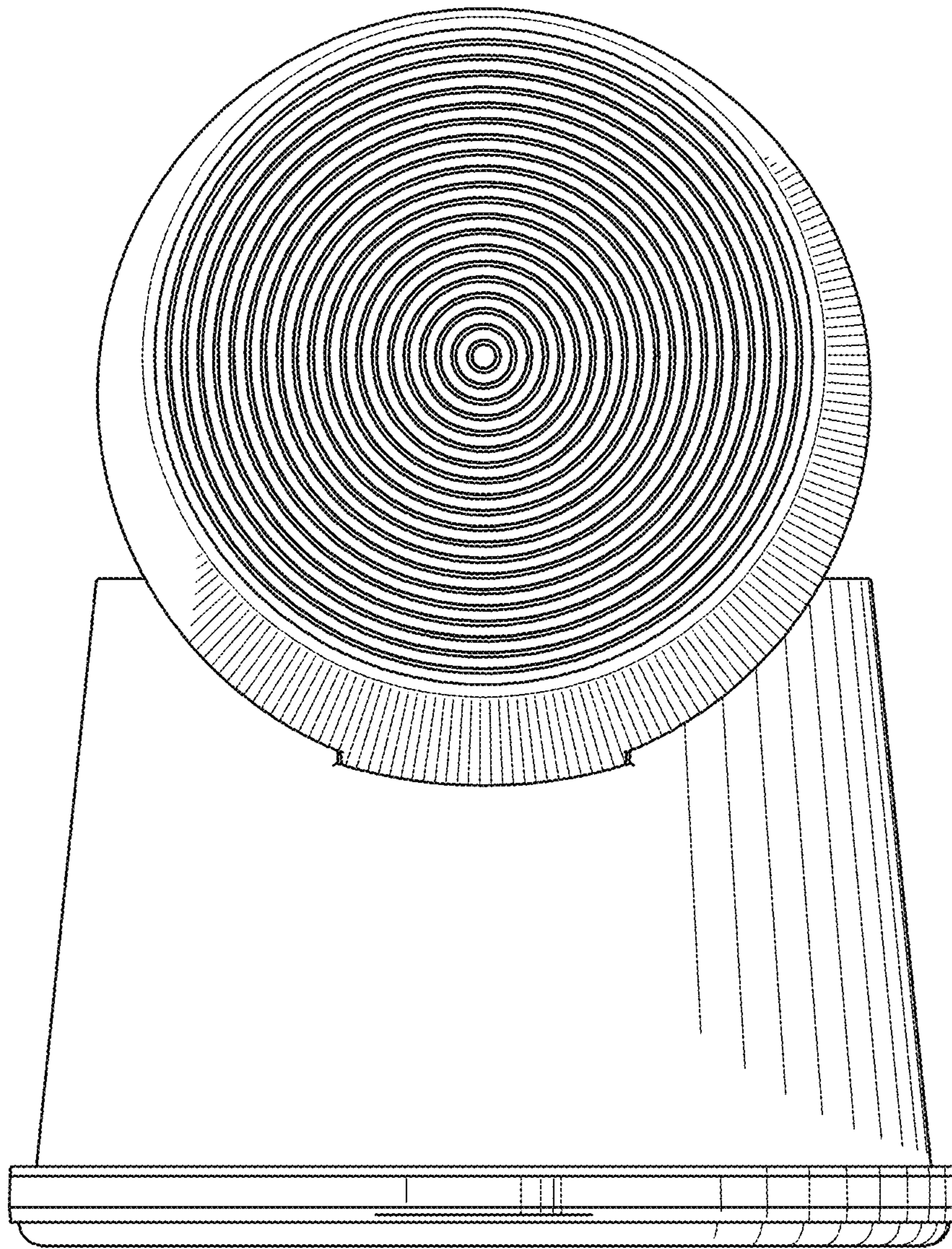


Fig. 17

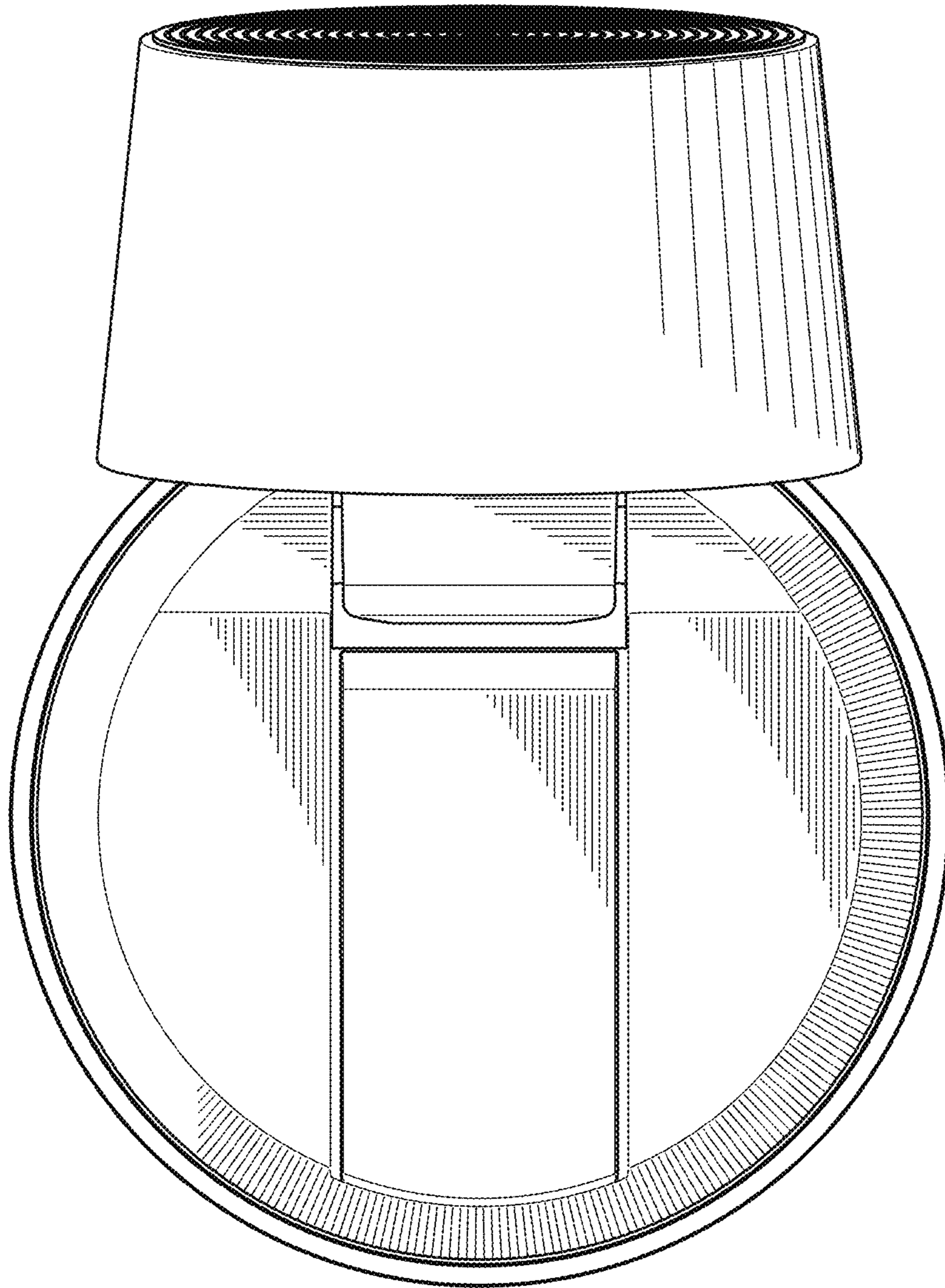


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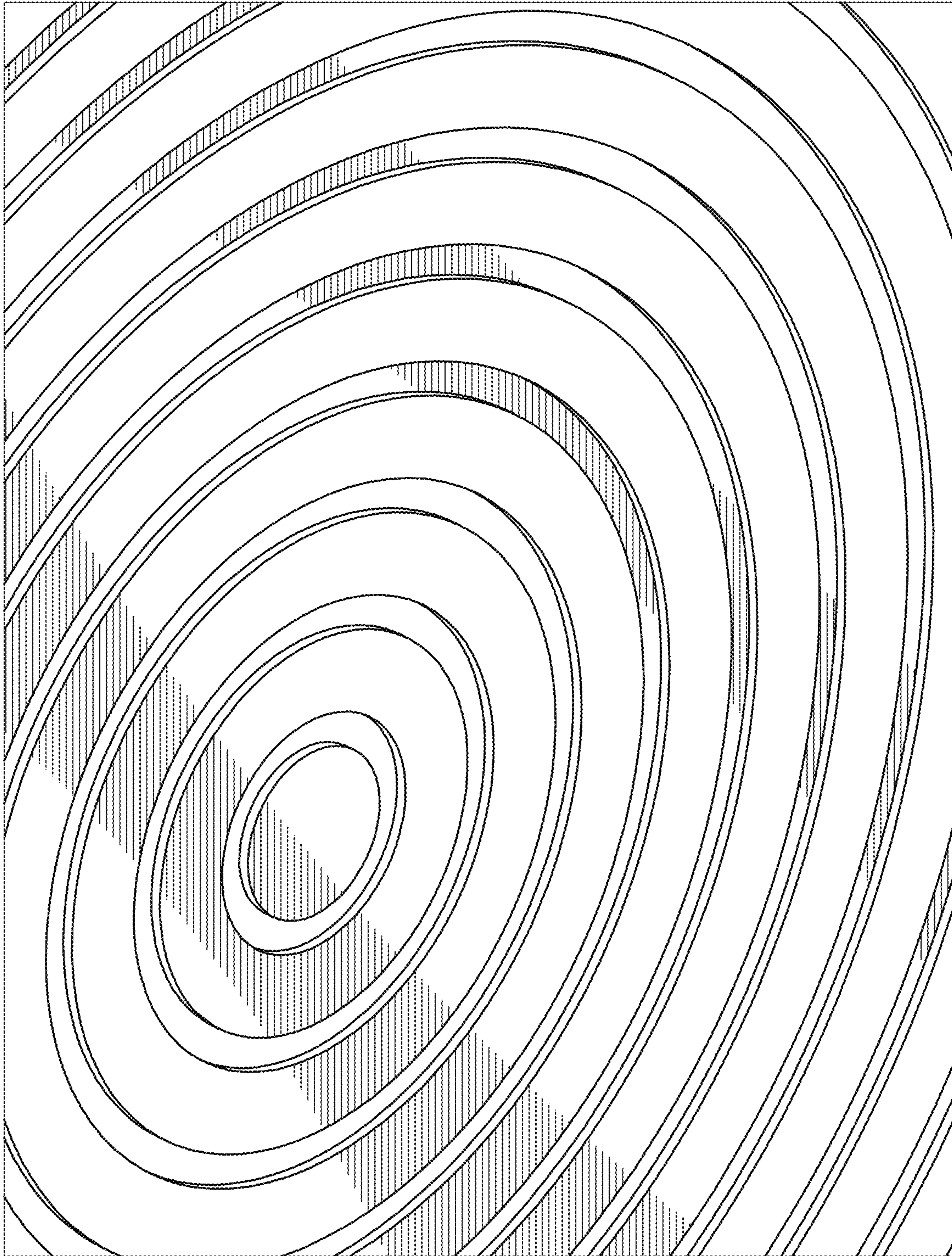


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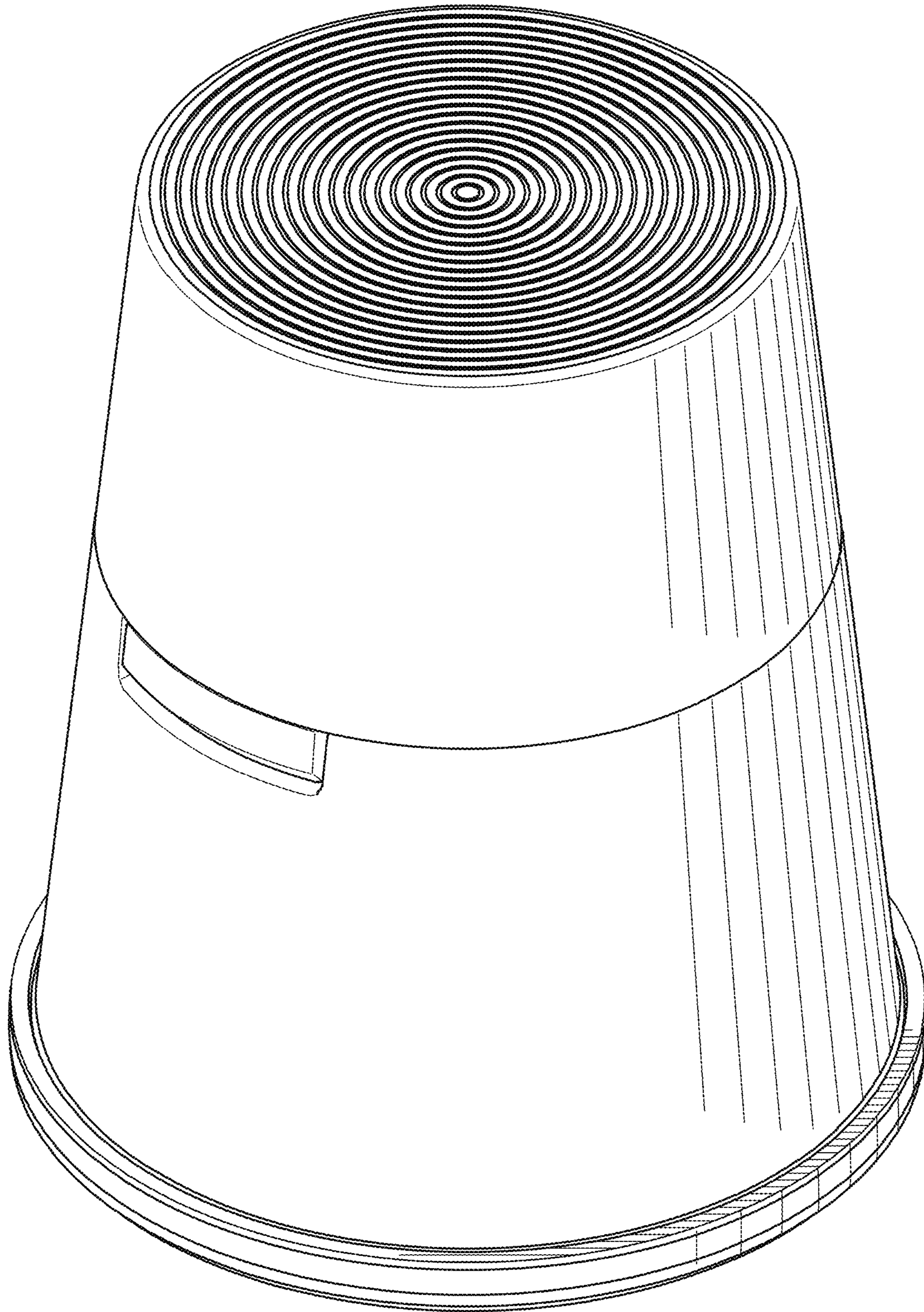


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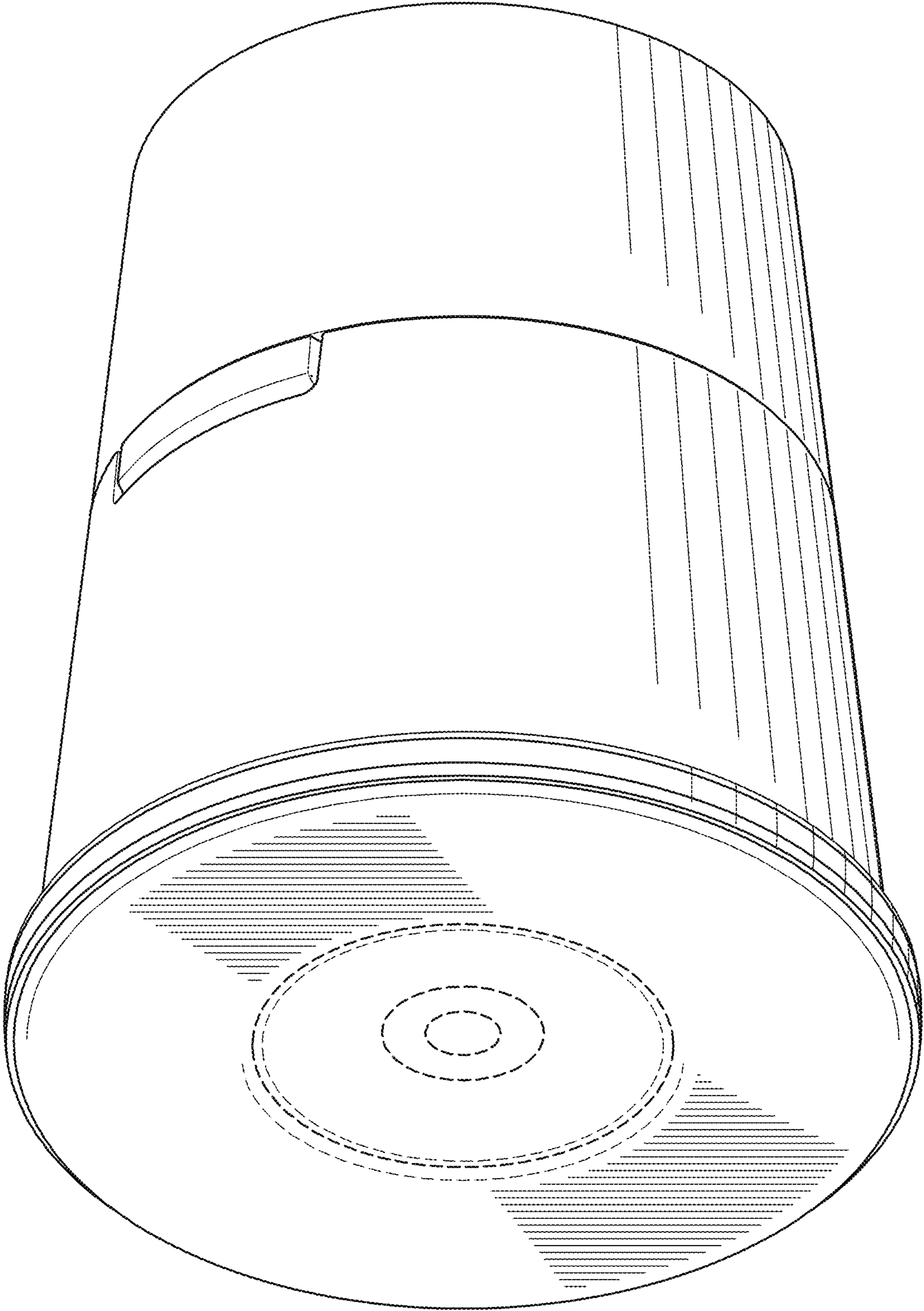


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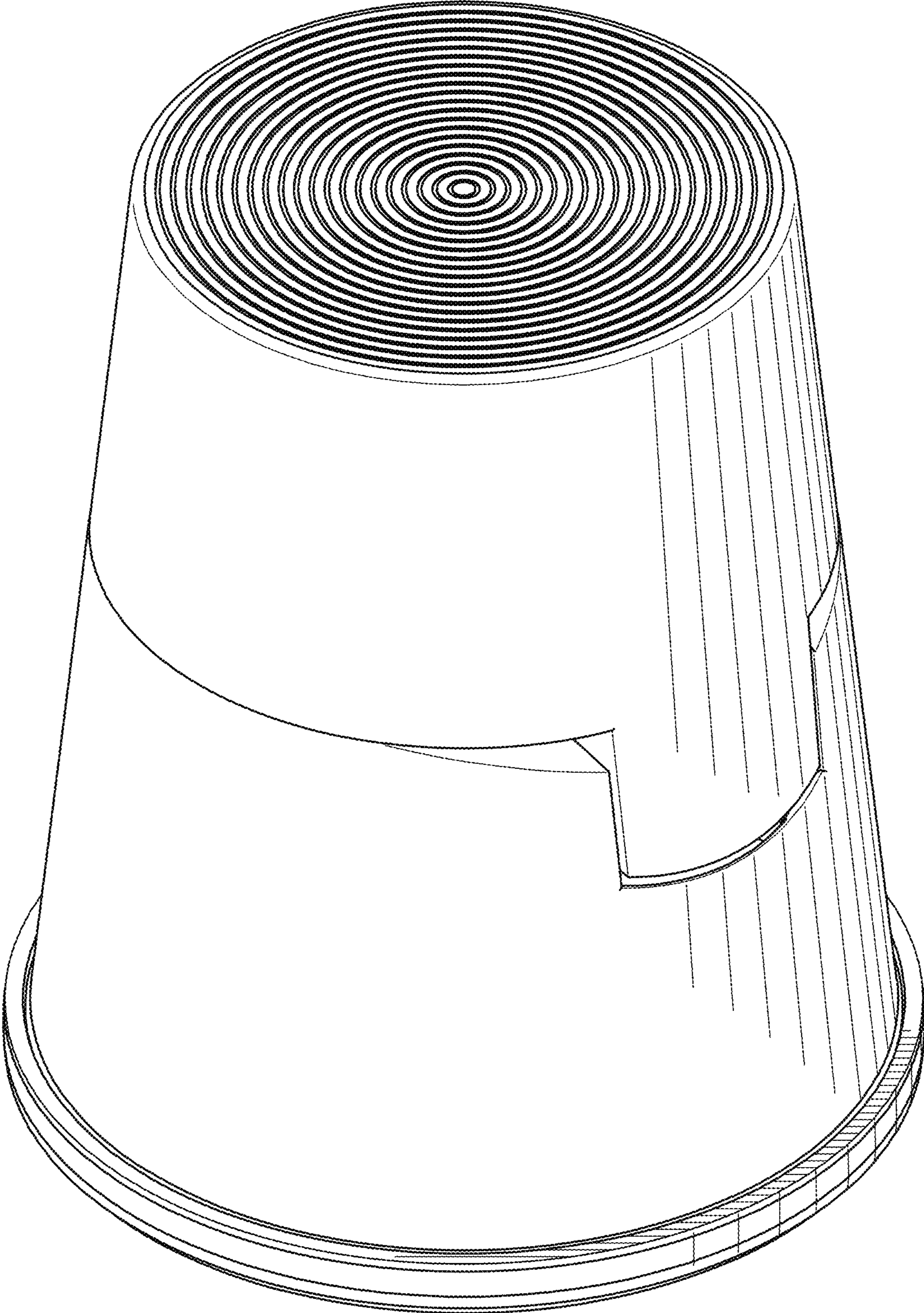


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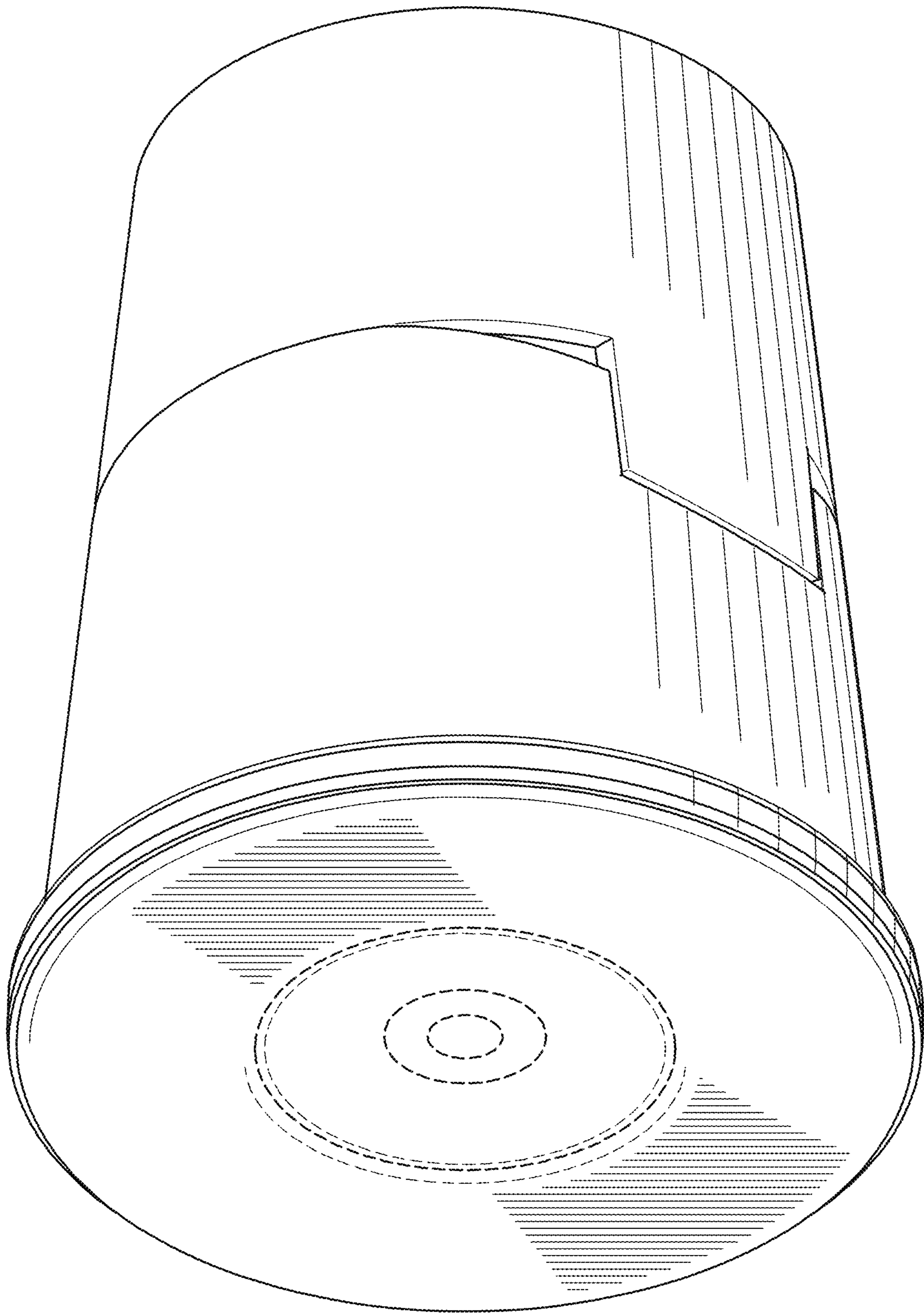


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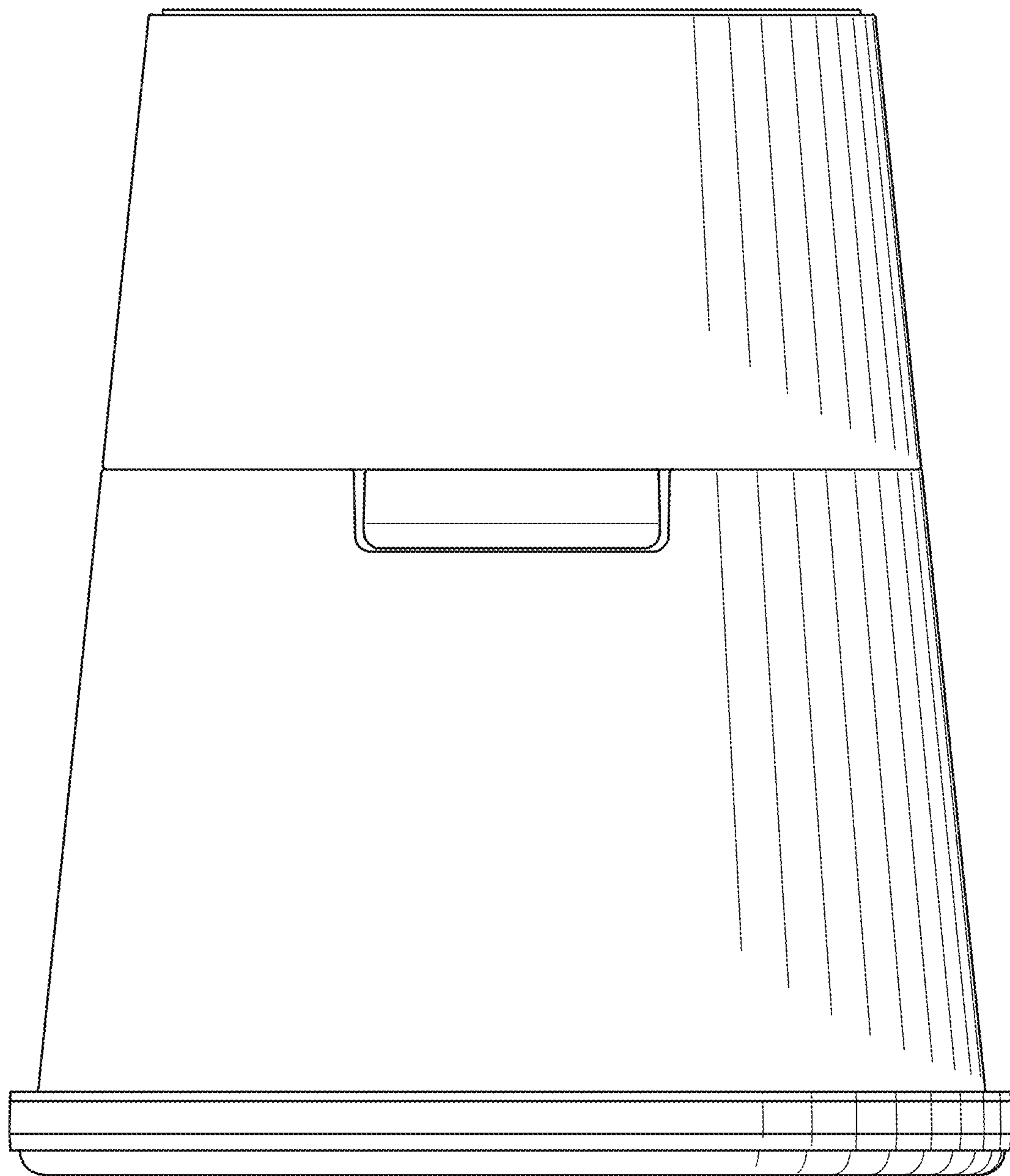


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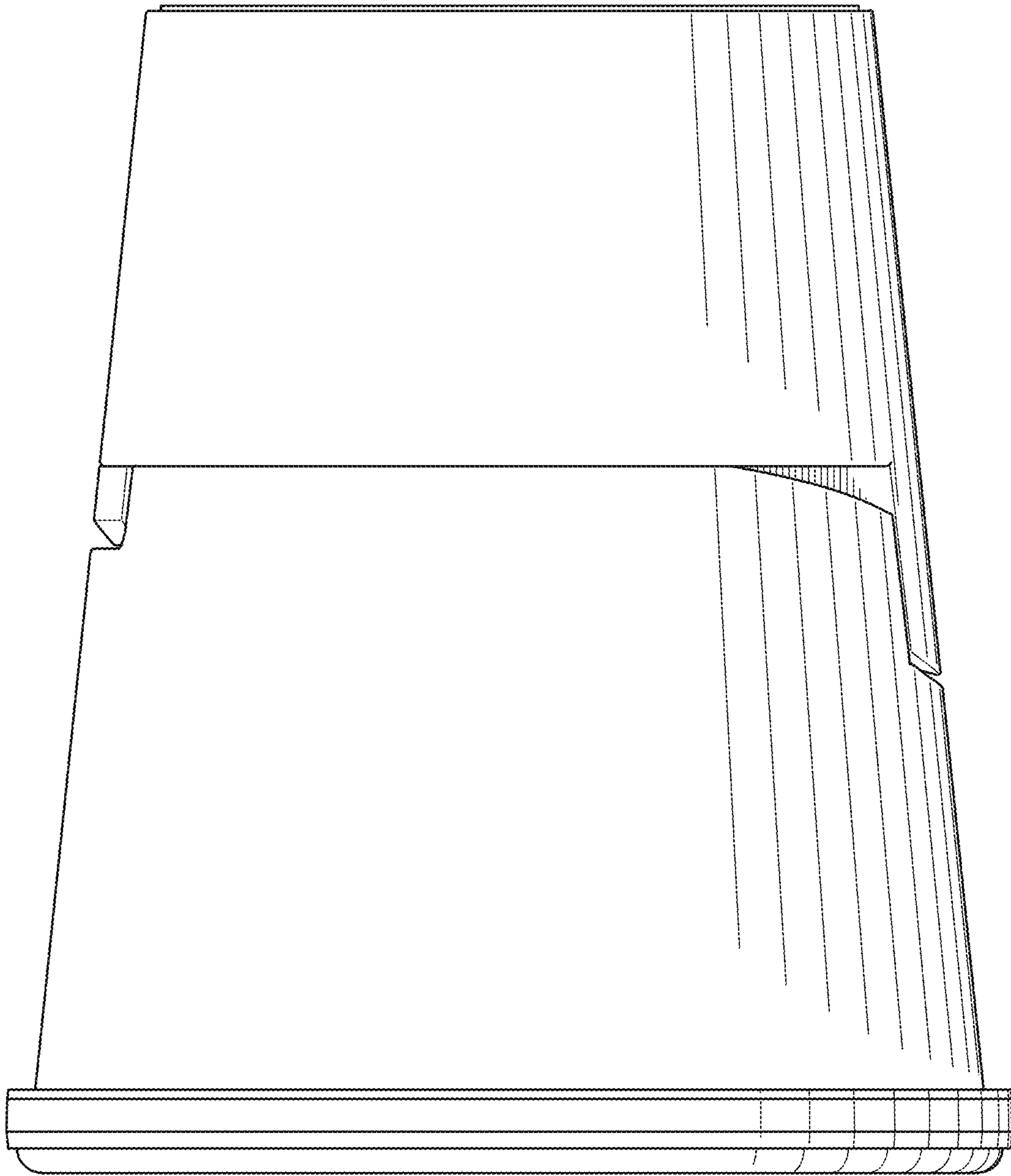


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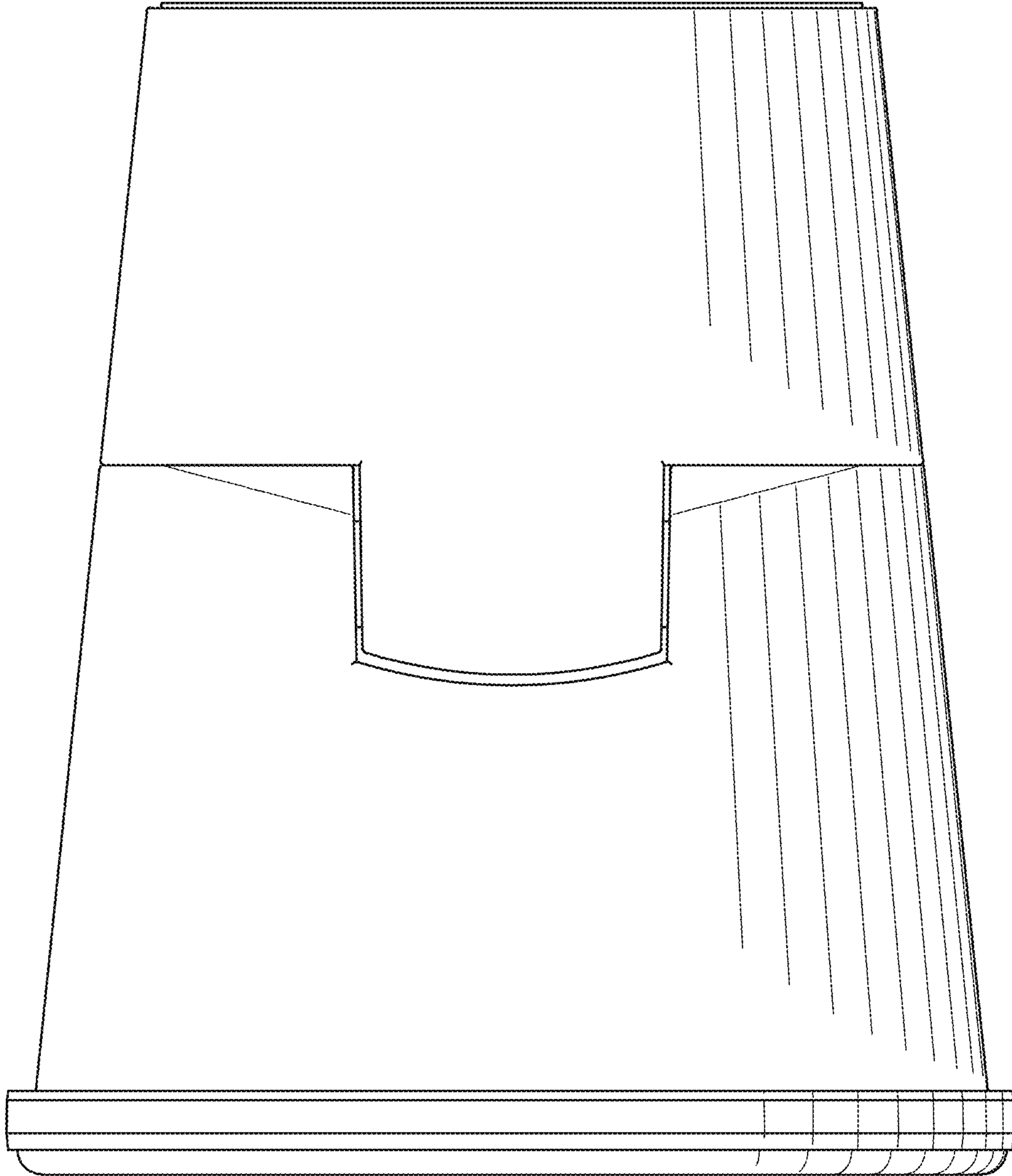


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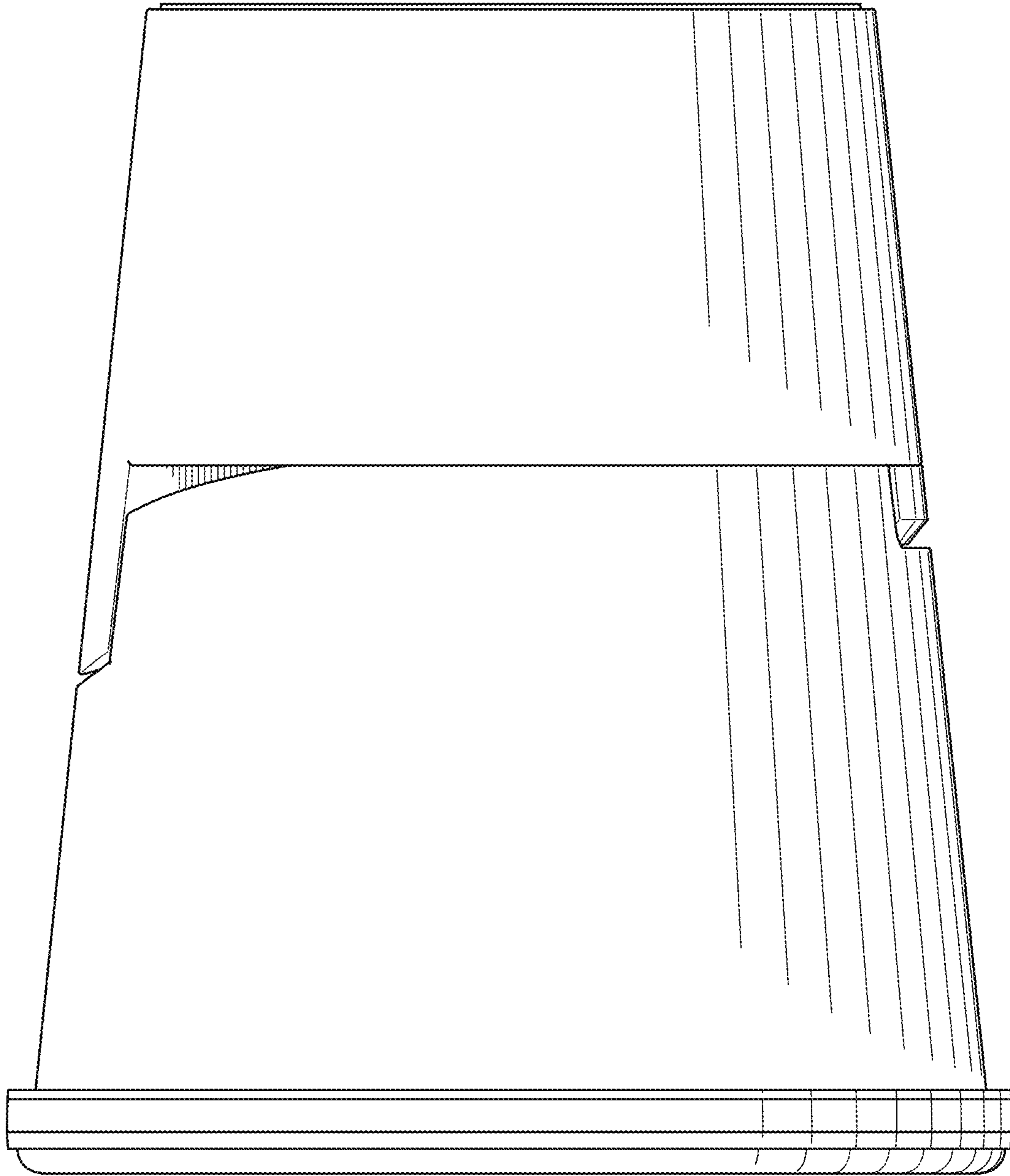


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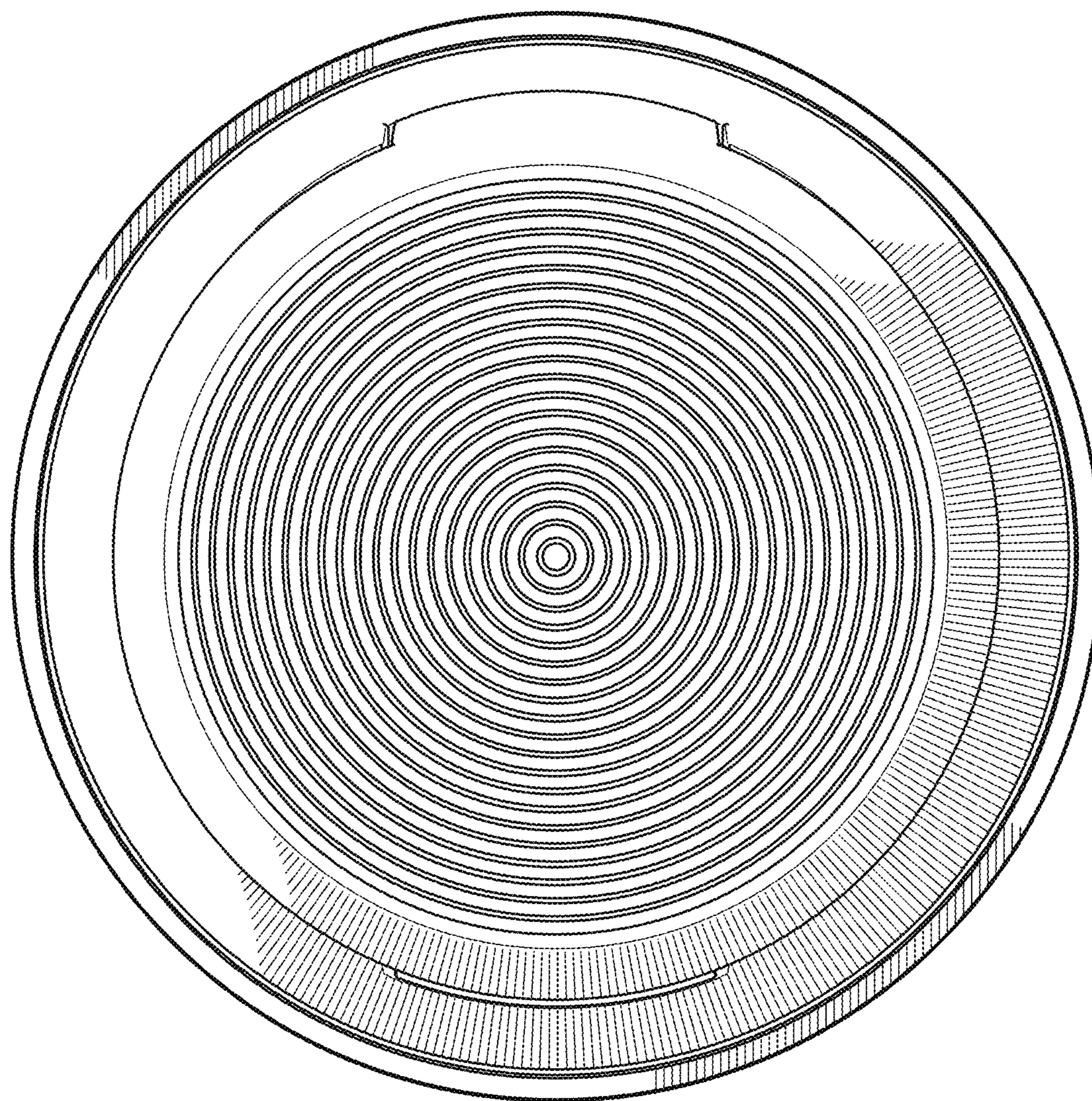


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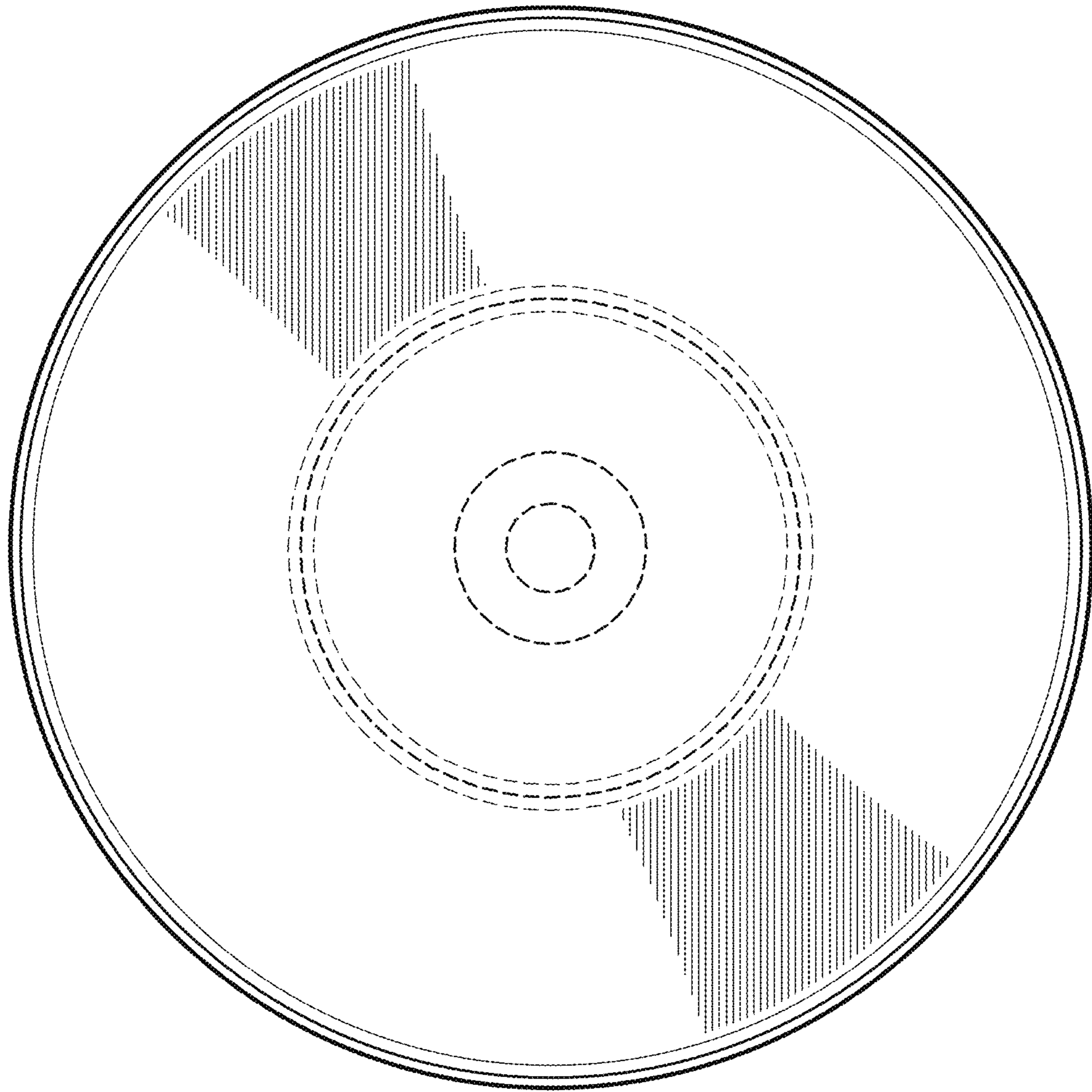


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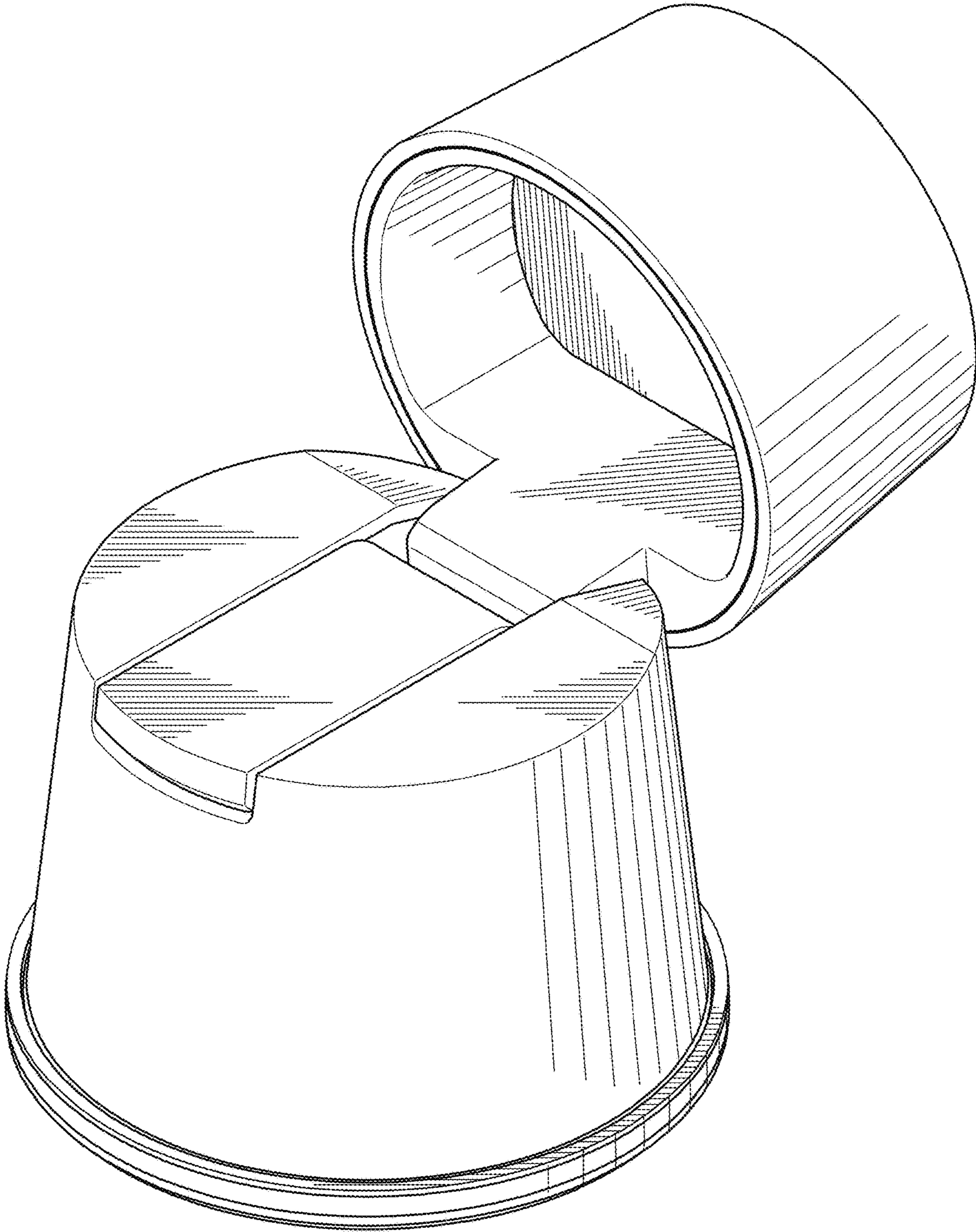


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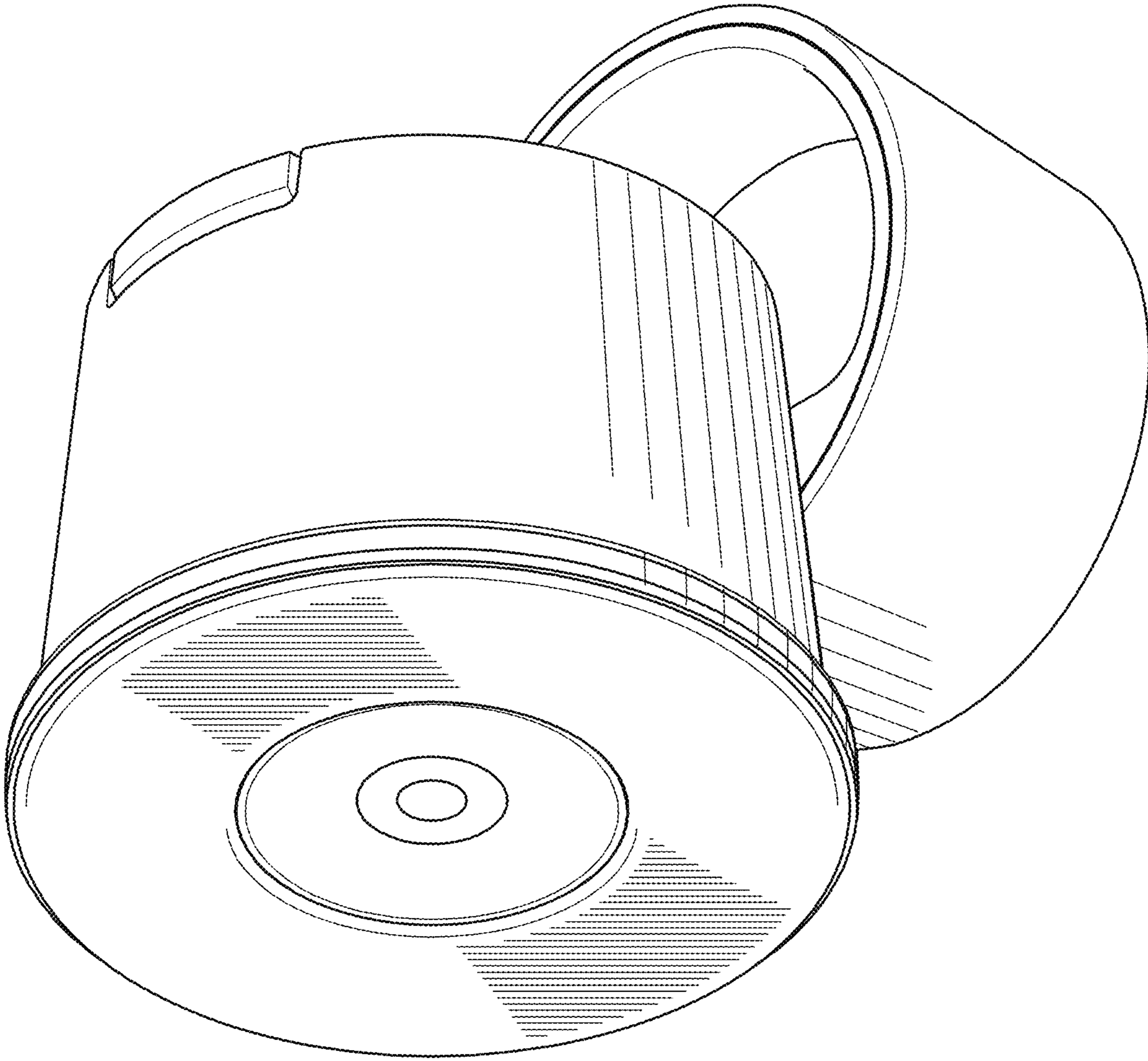


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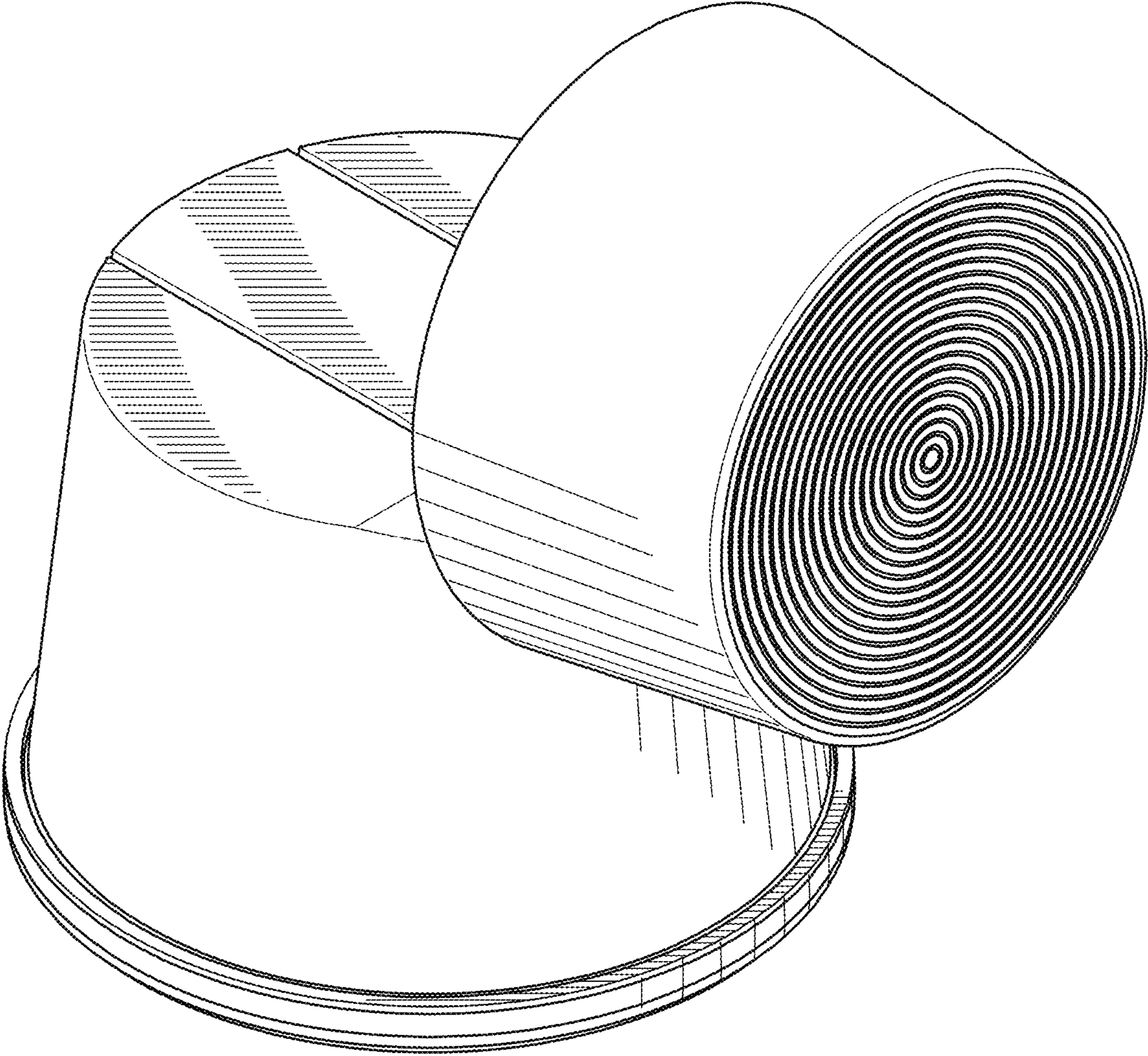


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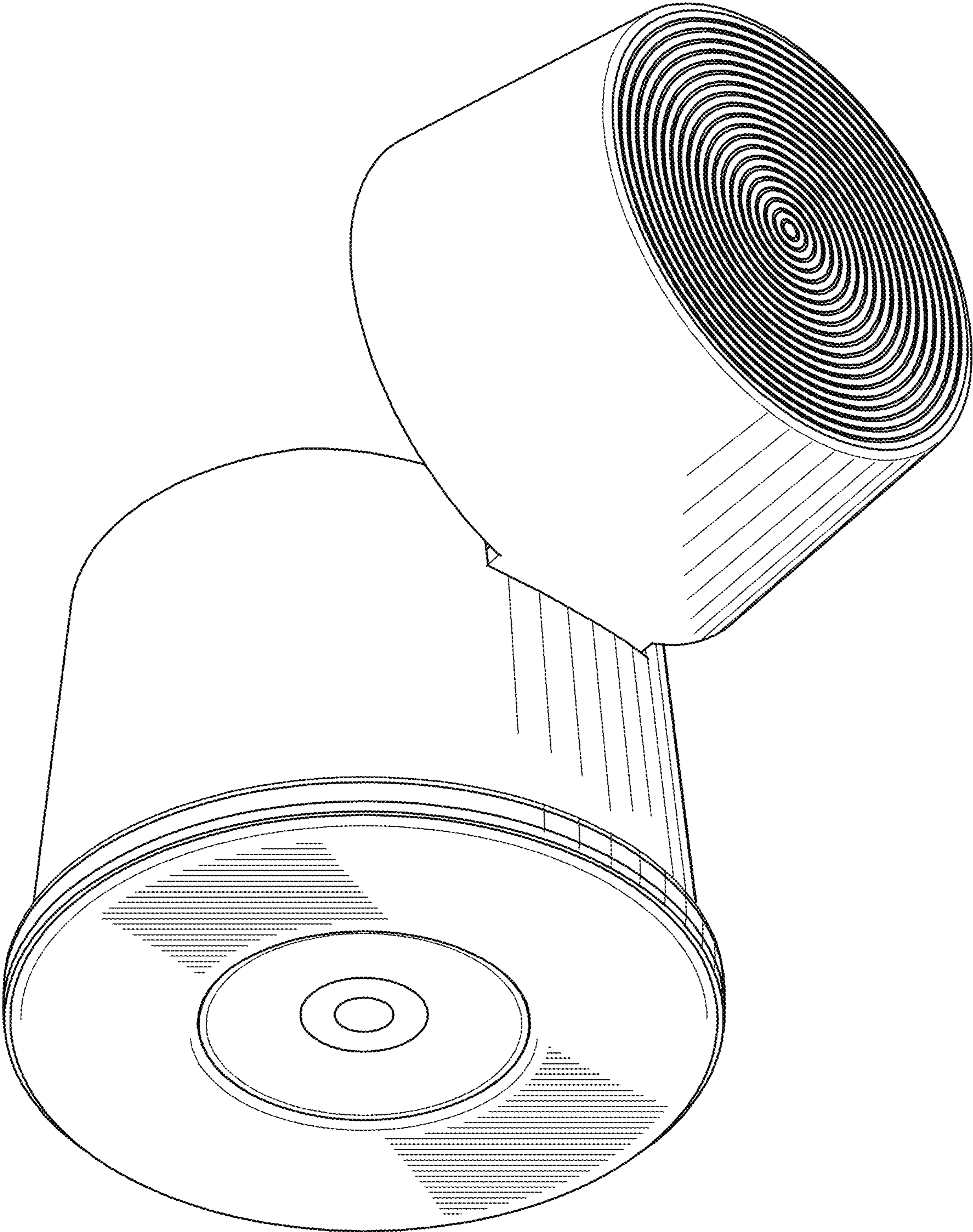


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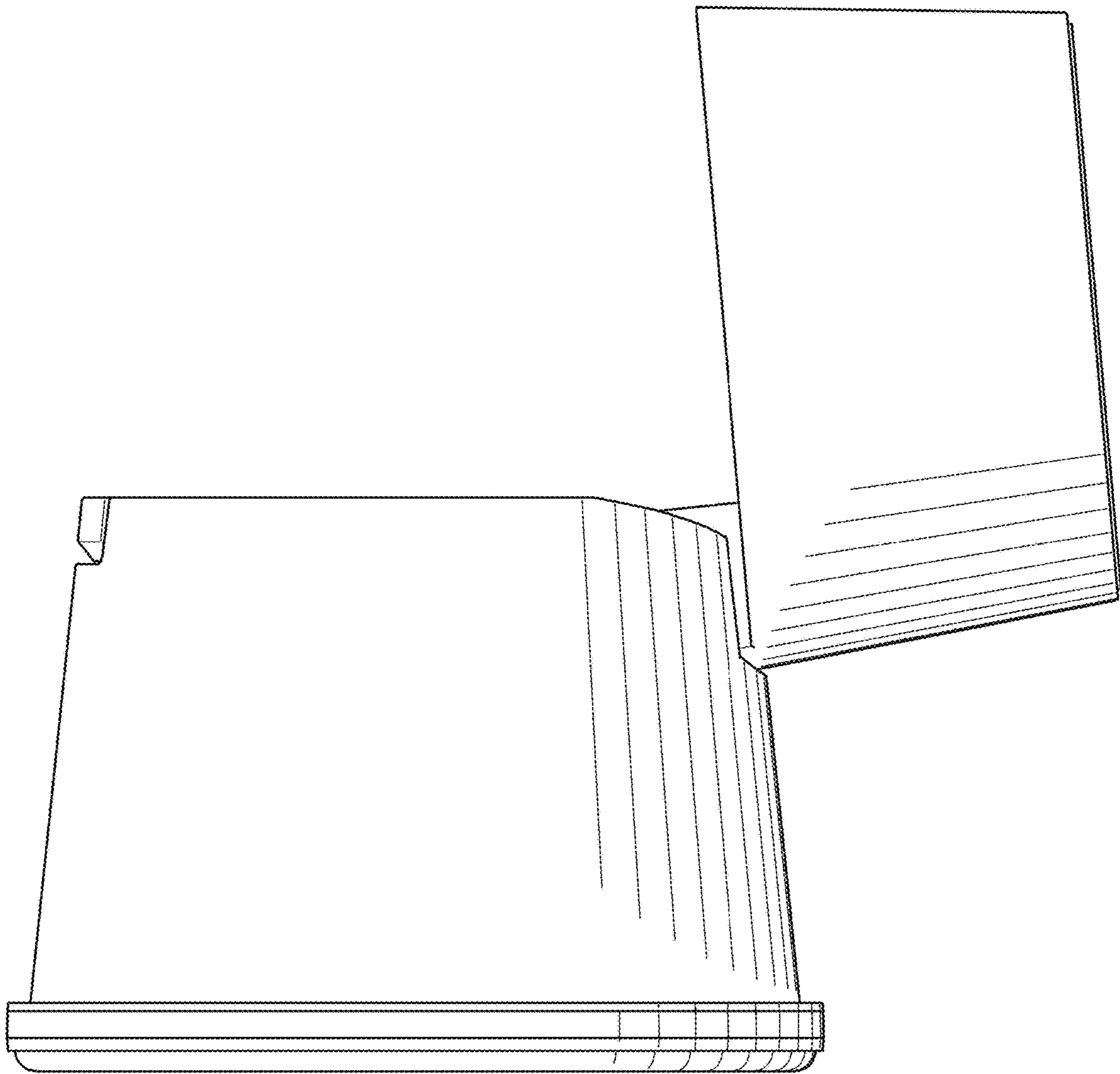


Fig. 34

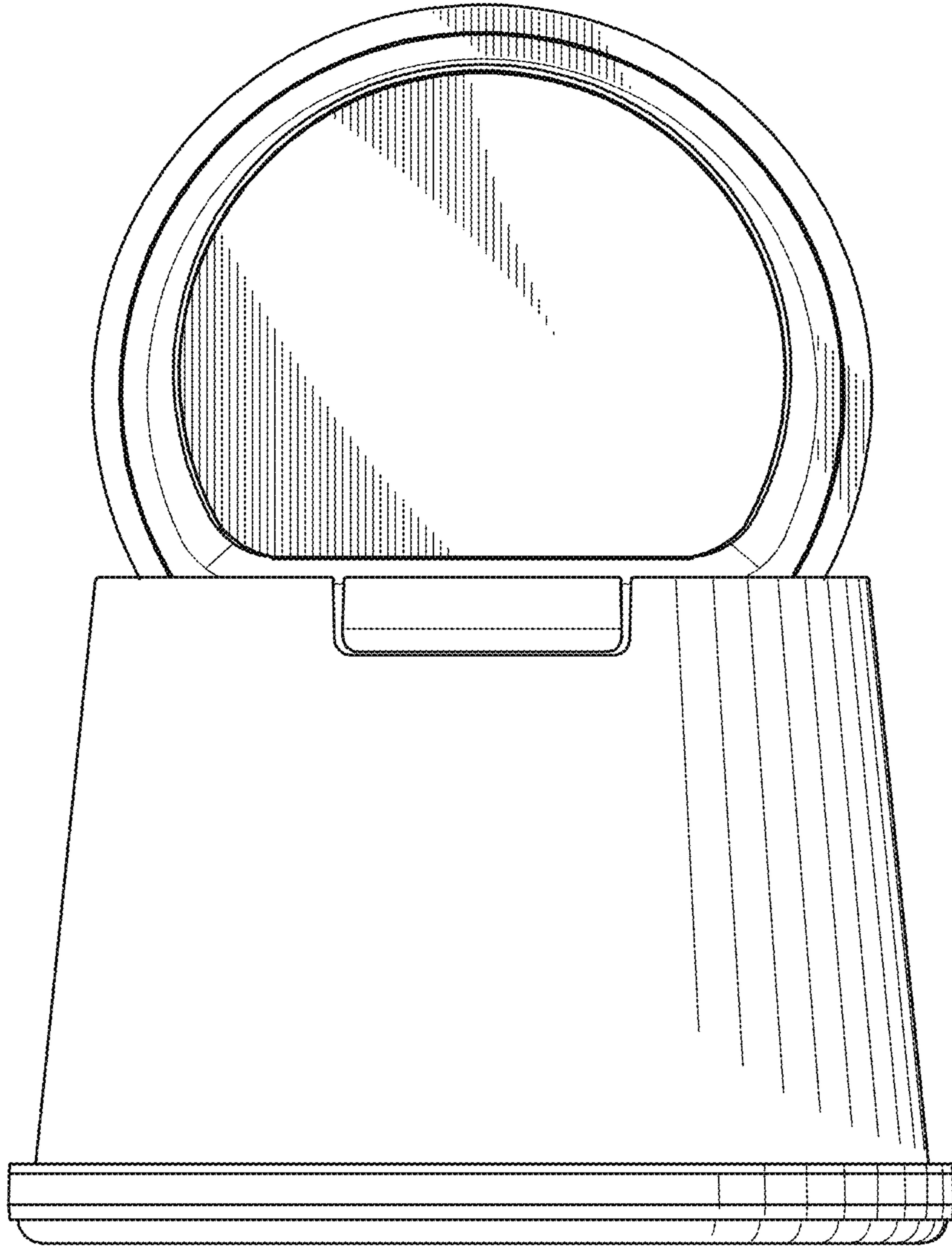


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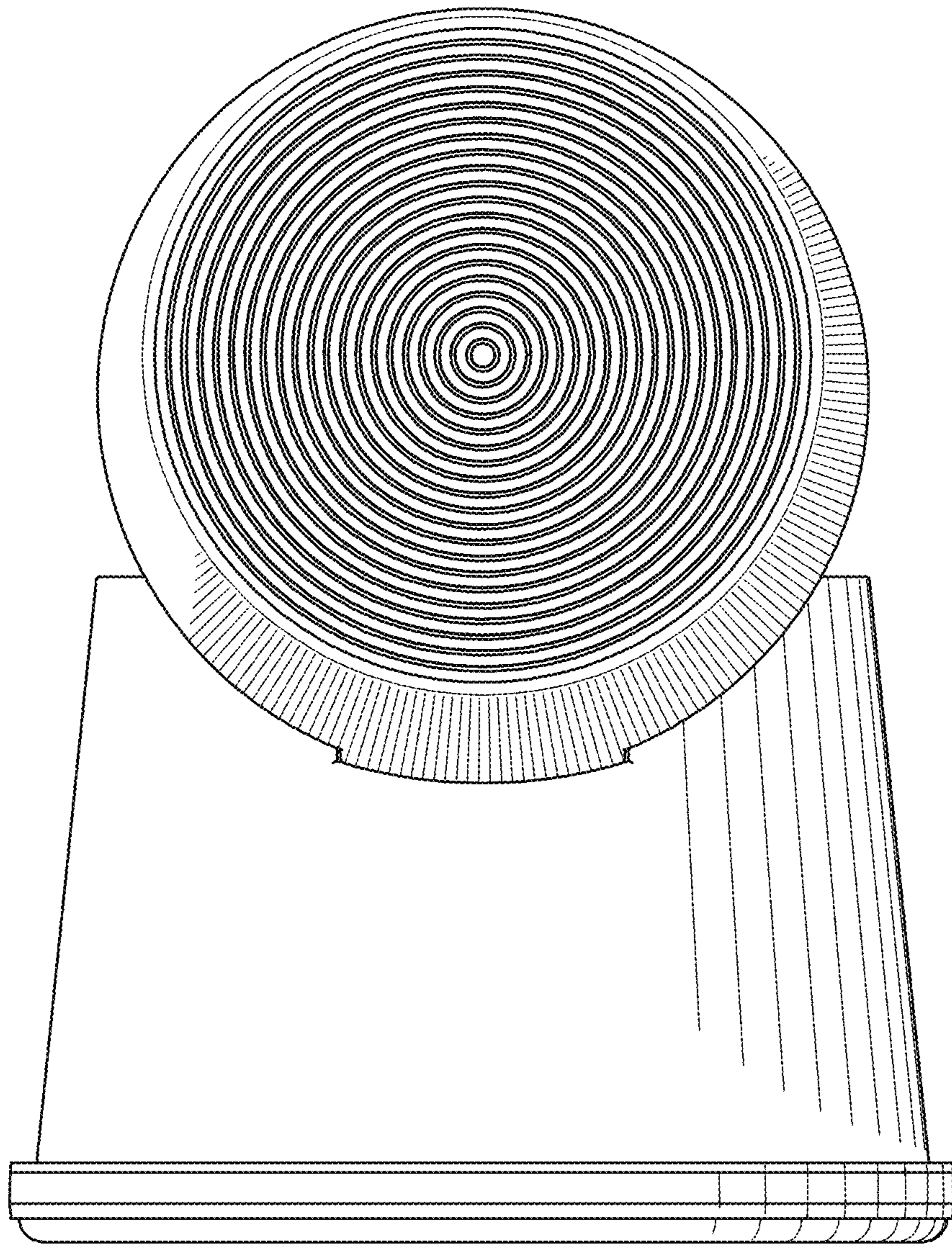


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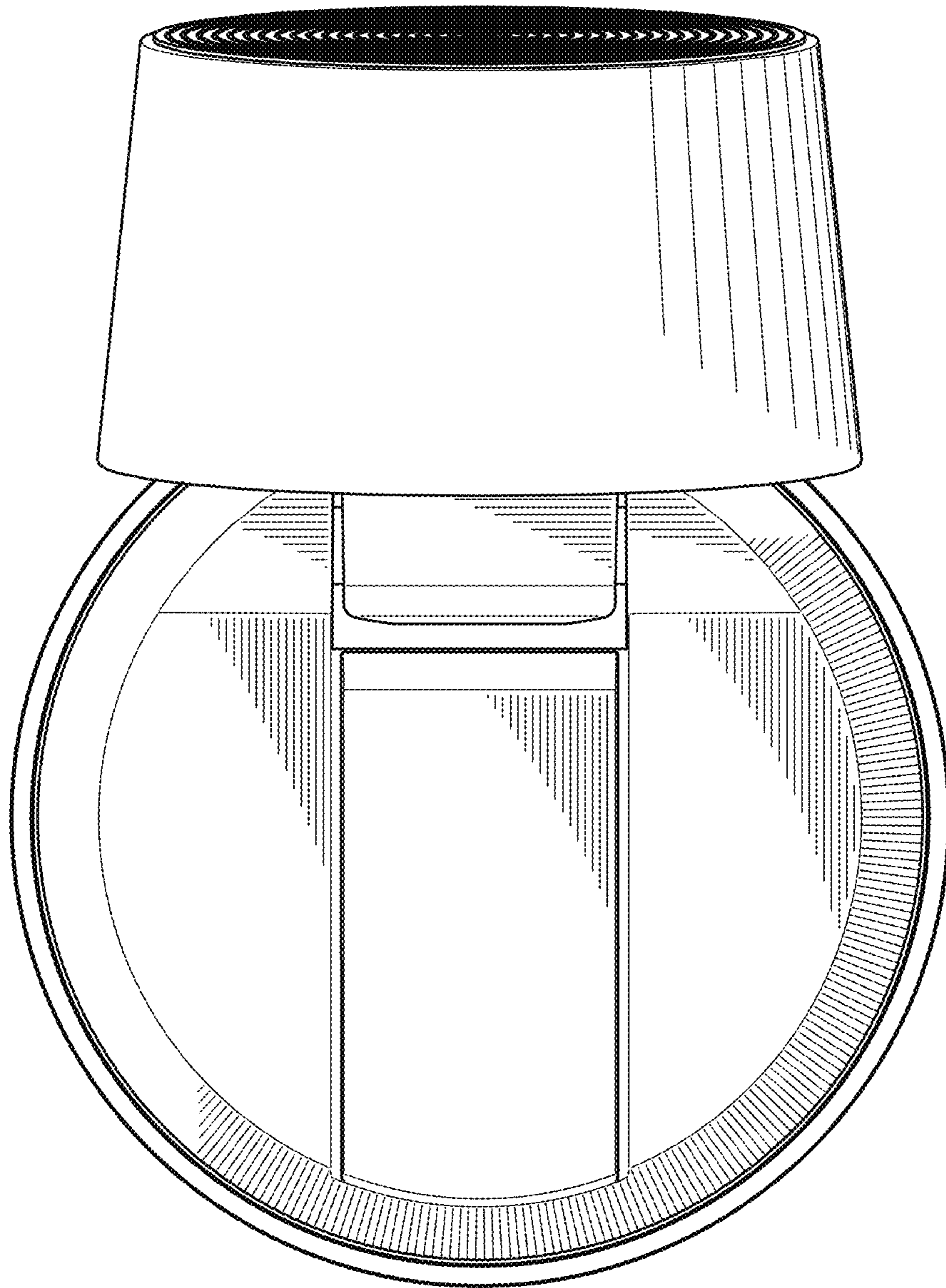


Fig. 37

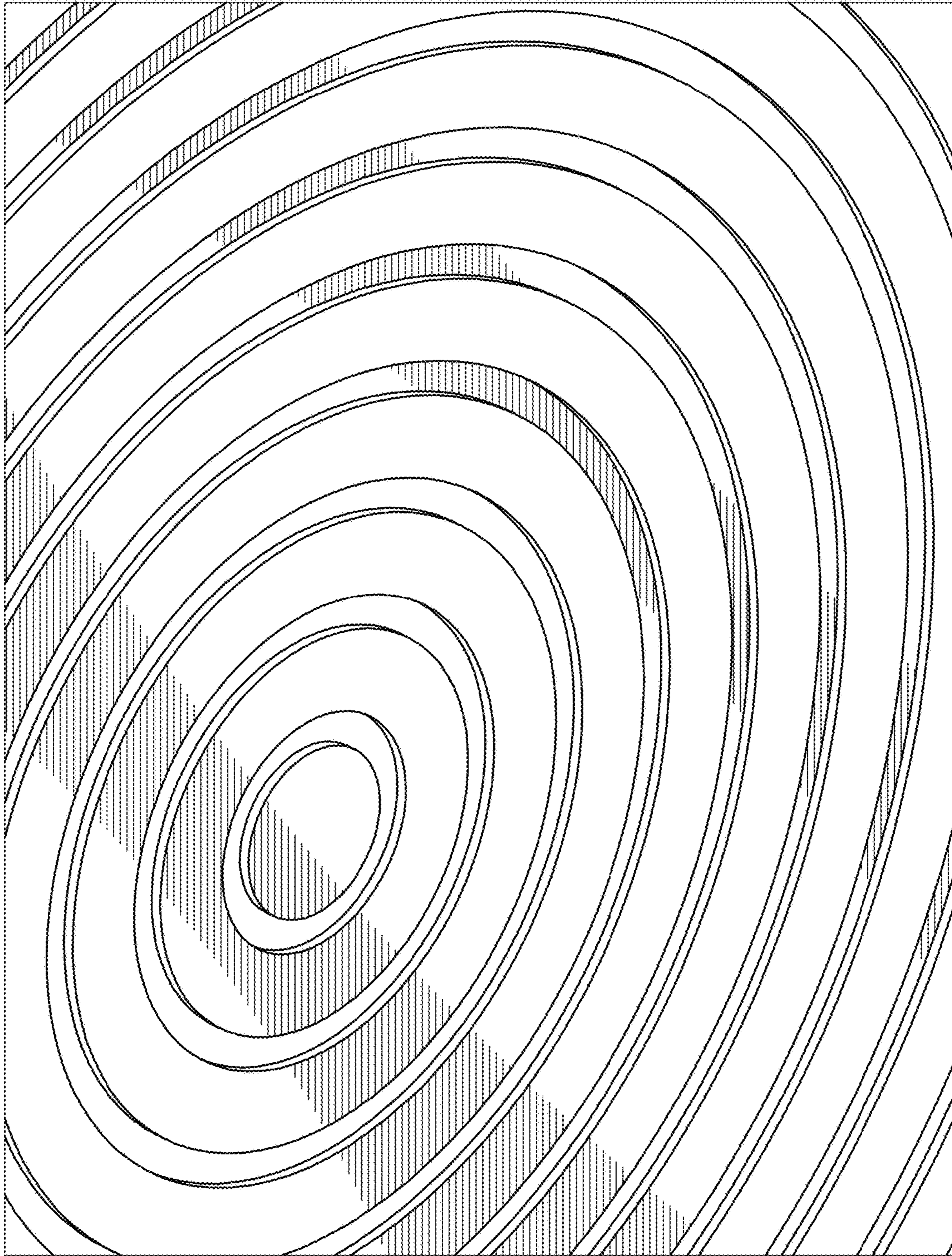


Fig. 38